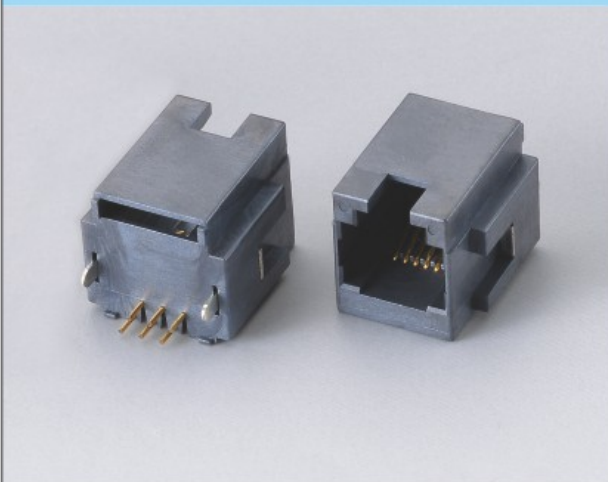


RJ11 NETWORK JACK VE TYPE



NOTE:

CAVITY CONFIRMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

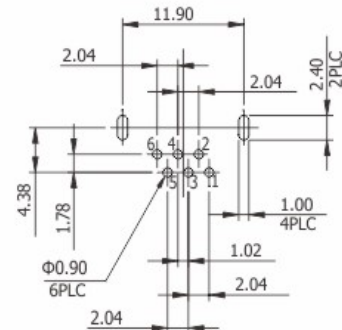
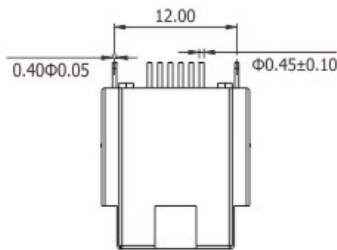
1. MATERIAL:

- 1.1 HOUSING: LCP, WITH GLASS FIBER,
- 1.2 CONTACTS: PHOSPHOR BRONZE.
- 1.3 HOOK: BRASS.

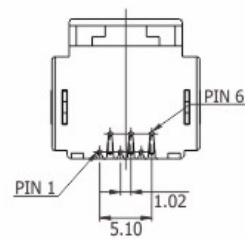
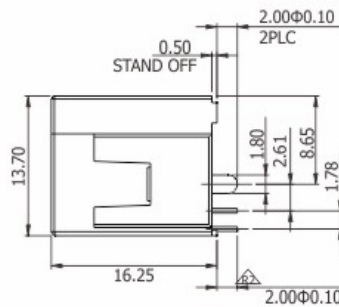
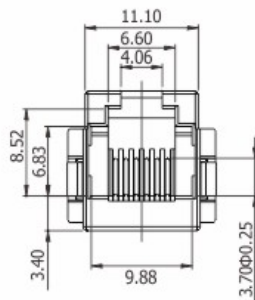
2. FINISH:

2.1 CONTACTS: 0.152mm [6μ"] GOLD PLATED ON ENTIRE CONTACT, 1.27mm [50μ"] MIN. NICKEL UNDERPLATED OVERALL.

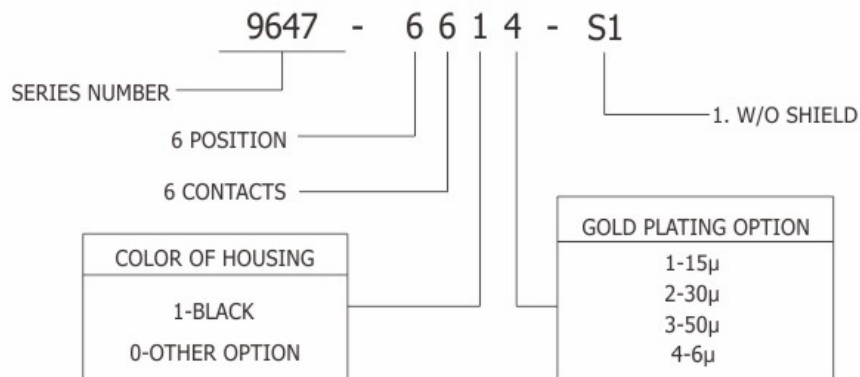
2.2 HOOK: 1.27mm [50μ"] MIN. TIN PLATED.



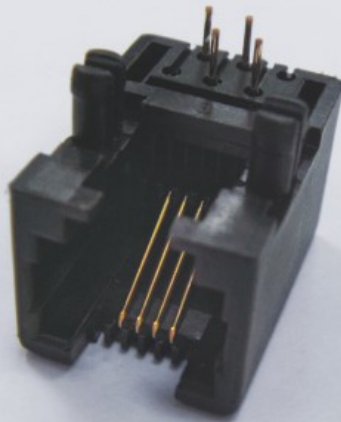
RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05mm (TOP VIEW)



Ordering Information



RJ11 DIP TYPE



NOTE:

1.MATERIAL:

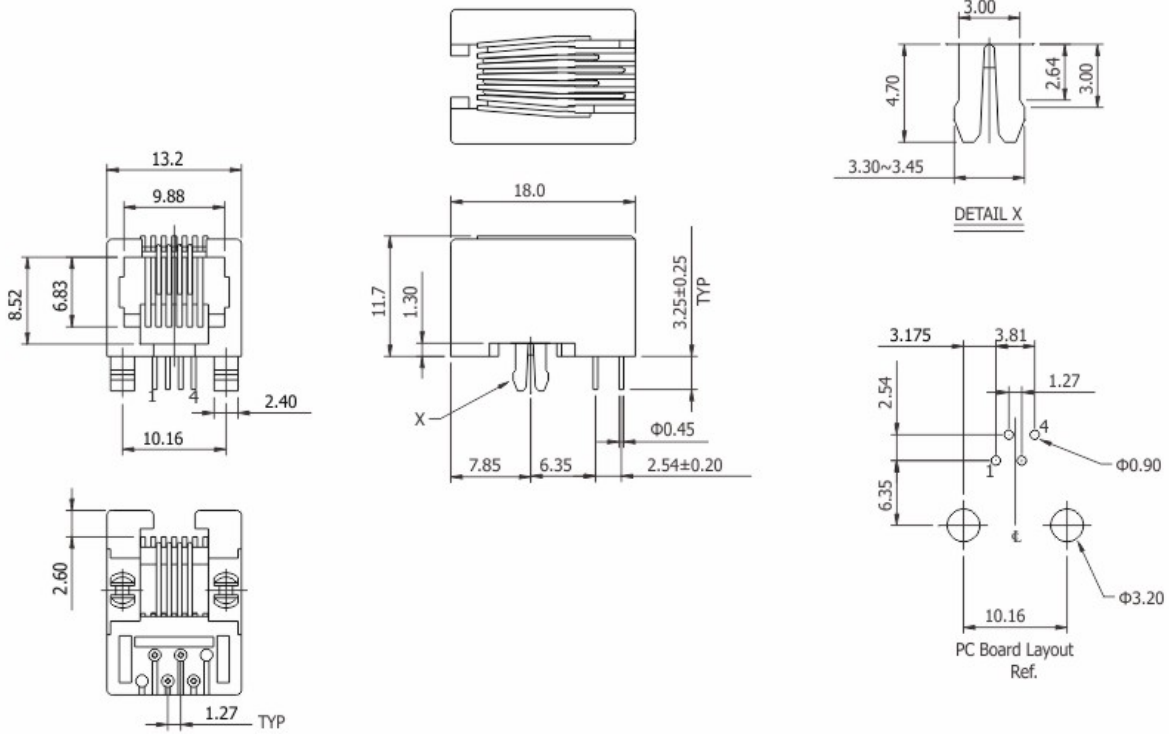
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
 CONTACT: C5191-EH, T=0.45±0.02

2.PLATING:

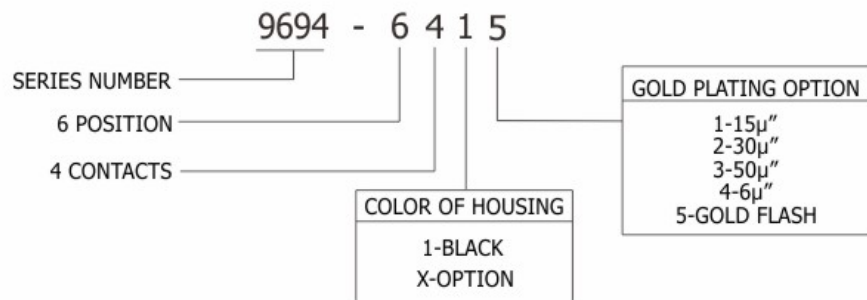
CONTACT: 30μ" Min Au over 50μ" Min Nickel

3.ELECTRICAL

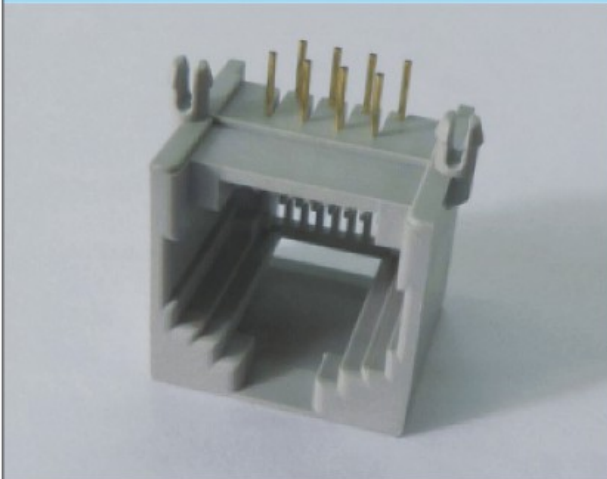
VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS MIN
 CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL
 Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

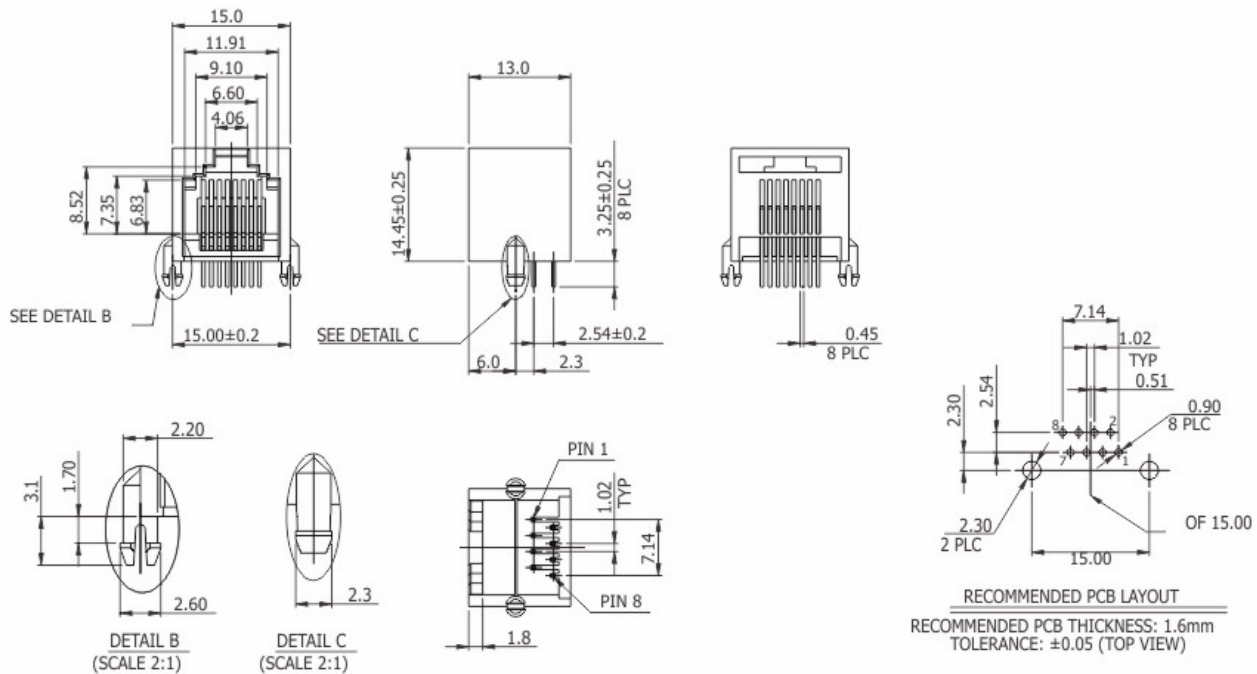
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
 CONTACT: C5191-EH, T=Φ0.45±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

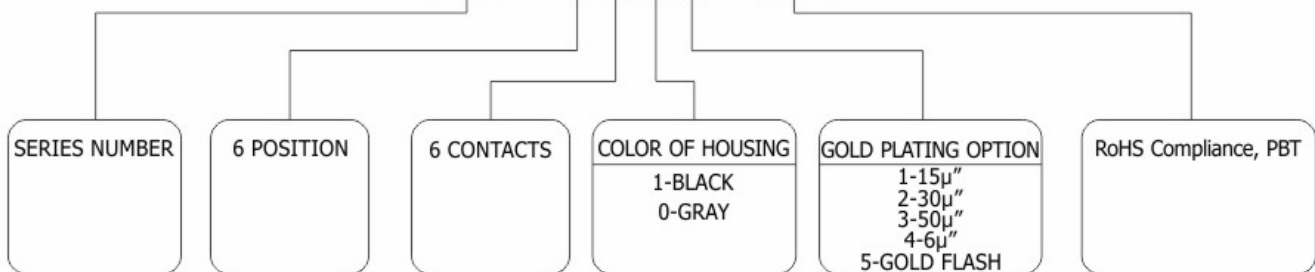
3.ELECTRICAL

VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS MIN
 CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL
 Storage Temperature: -20°C ~ +85°C



Ordering Information

9612 - 8 8 0 5 - LFG



RJ11 2*1 PORTS DIP TYPE



NOTE:

1.MATERIAL:

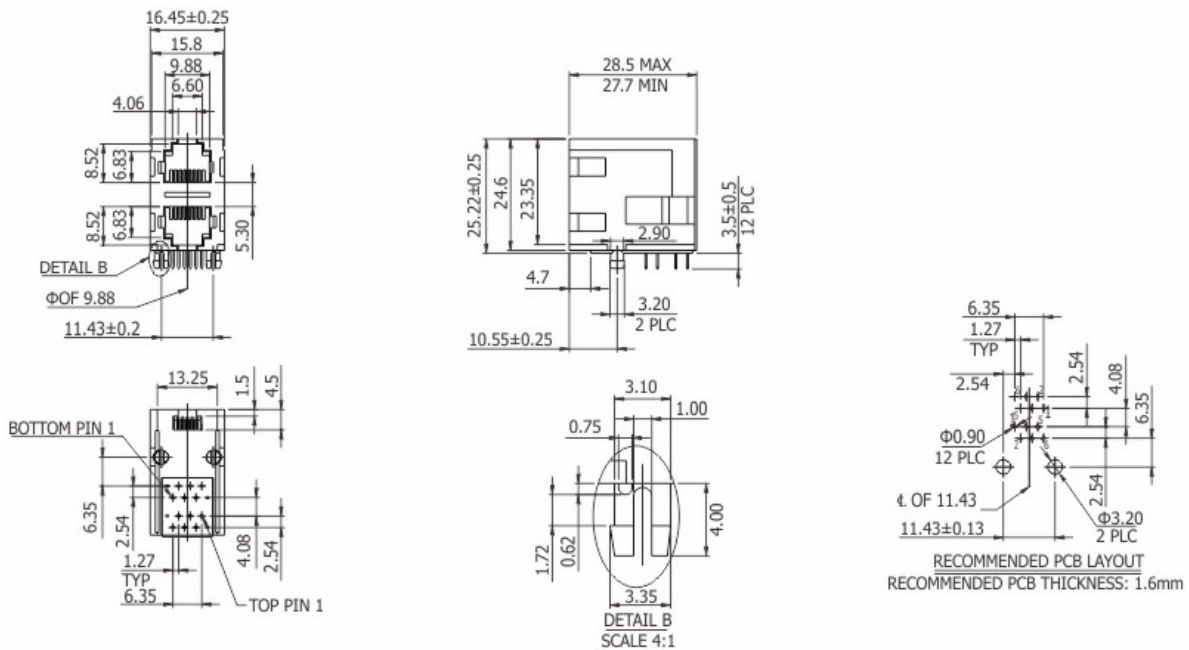
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
CONTACT: C5191-EH, T=0.35±0.02

2.PLATING:

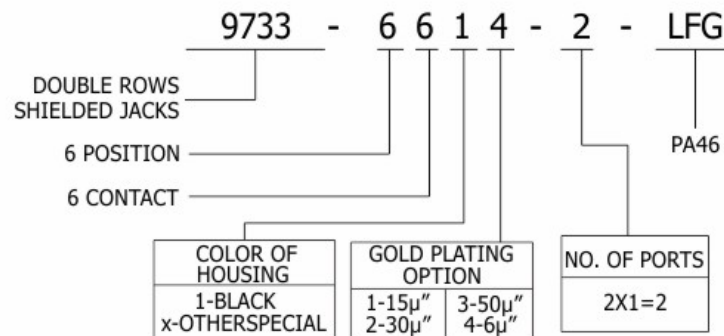
CONTACT: 30µ" Min Au over 50µ" Min Nickel

3.ELECTRICAL

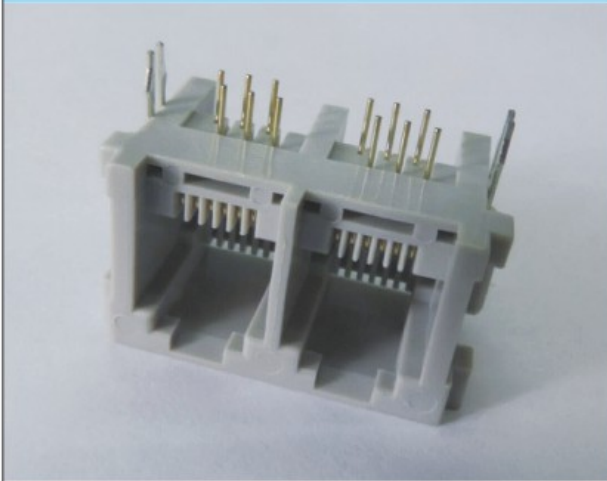
VOTAGE RATING: 150 VAC (R.M.S.)MAX
CURRENT RATING: 1.0 AMPERE MAX
INSULATION RESISTANCE: 500 MEGAOHMS MIN
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ11 1*2 PORTS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
CONTACT: C5191-EH, T=0.45±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

3.ELECTRICAL

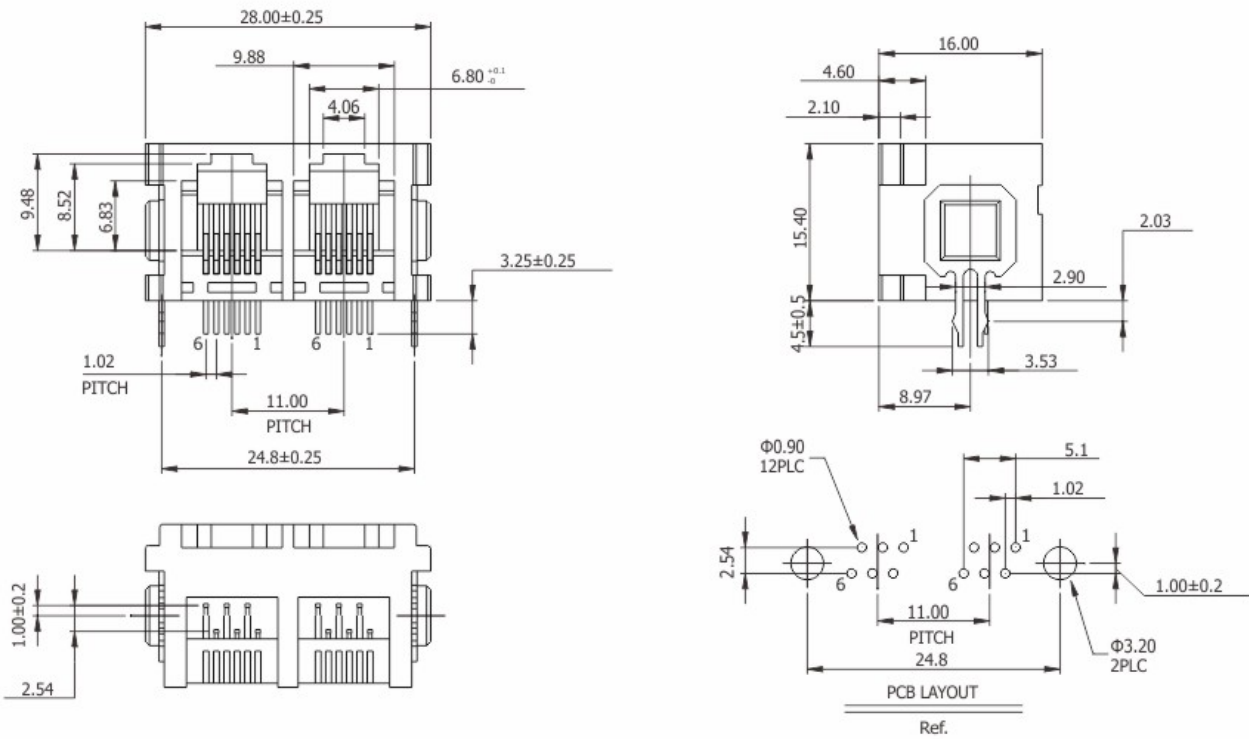
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

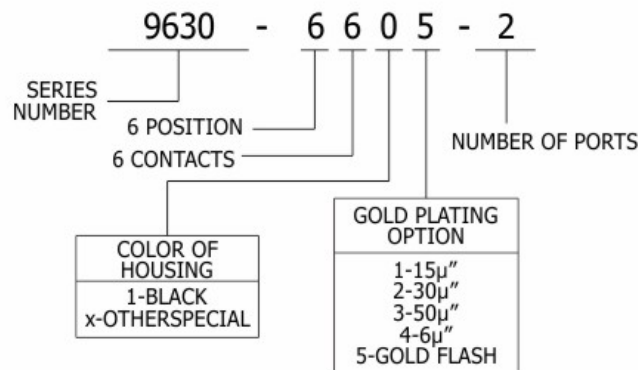
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

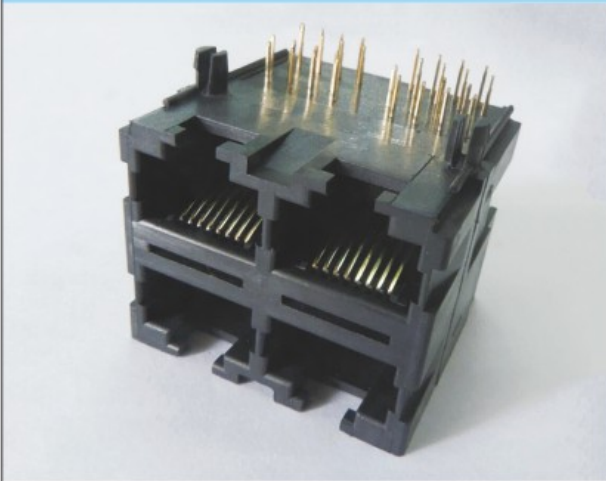
Storage Temperature: -20°C ~ +85°C



Ordering Information

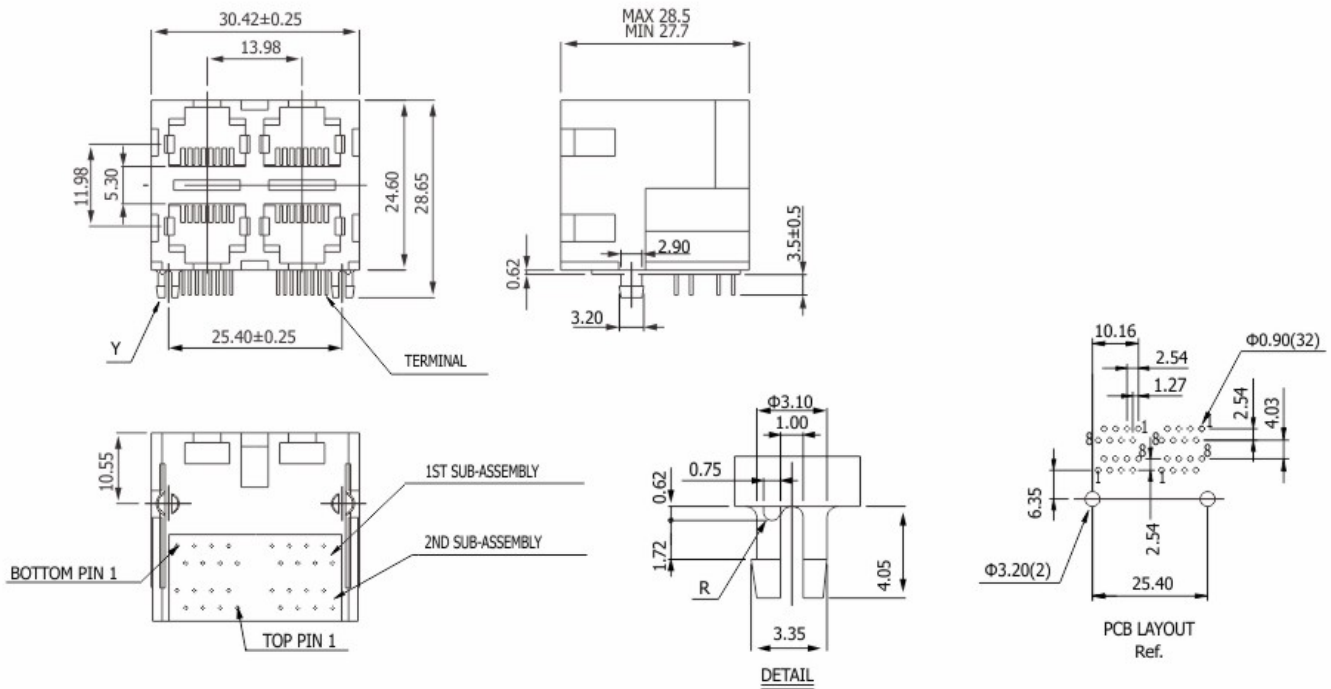


RJ45 2*2 PORTS DIP TYPE

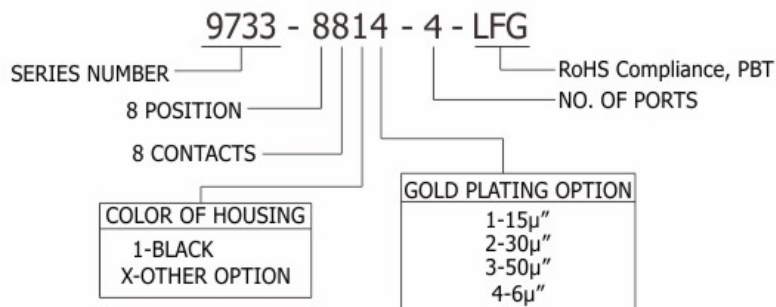


PRODUCT SPECIFICATION

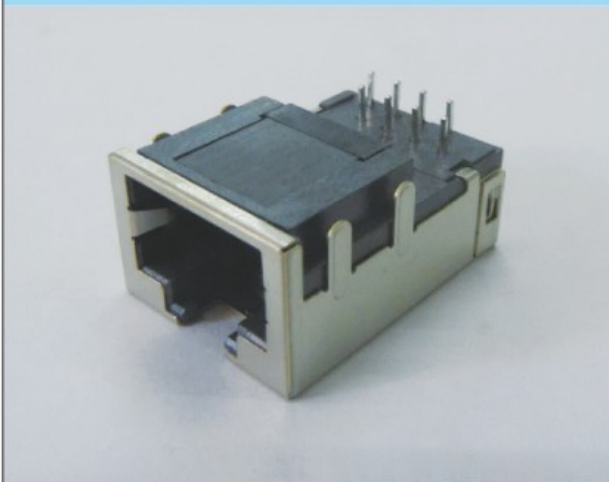
Material:
 SHELL: Brass
 PLASTIC: PBT color: BLACK 94V-0
 CONTACT: PHOSPHOR-BRONZE
 PLATING:
 TERMINAL: Contact Plating: 1μ" gold over 50μ" Nickel min.
 Solder Tail: 120μ"min Tin over 50μ" Nickel min.
 SHELL: Plating 80μ" Nickel min.



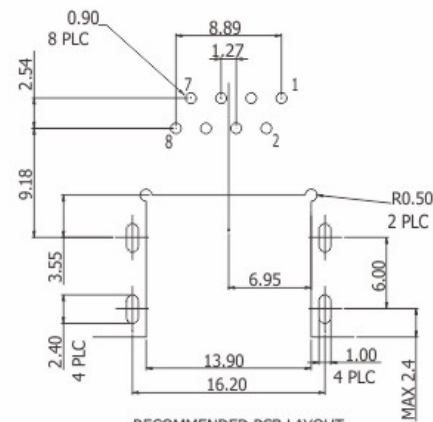
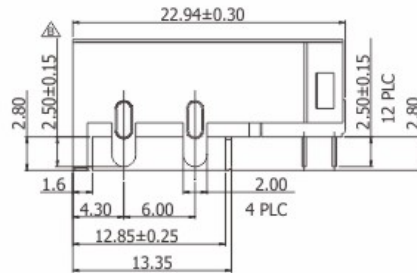
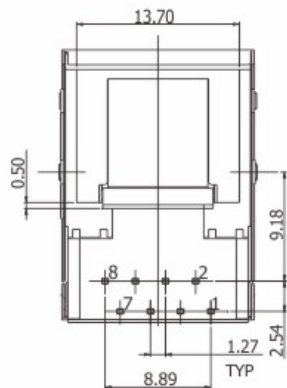
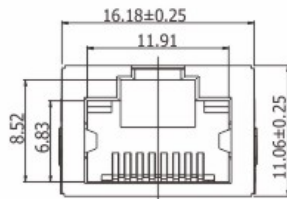
Ordering Information



RJ45 SINKING 10/100 MBPS DIP TYPE

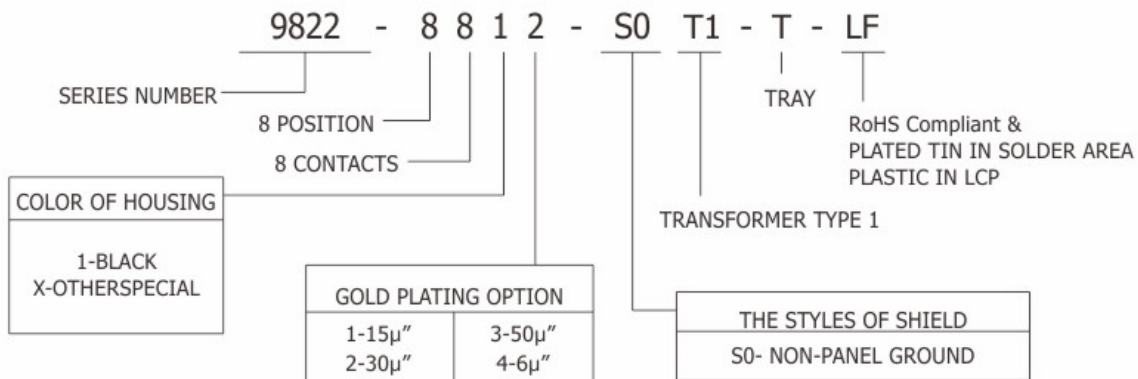


MATERIAL:
 HOUSING-LCP, UL94V-0
 HEAT DEFLECTION TEMP.265°
 STANDARD COLOR-BLACK
 CONTACTS T=0.35mm THICK PHOS-BRONZE PLATED
 WITH 30μ" HARD GOLD
 SOLDER TAIL T=0.35mm THICK BRASS PLATED
 WITH 100μ" TIN
 SHIELD T=0.20mm THICK COPPER ALLOY,
 PLATED WITH NICKEL.
 CAVITY CONFIRMS TO FCC RULES AND REGULATIONS
 PART 68, SUBPART F.



RECOMMENDED PCB LAYOUT
 FOR 1.2MM THICKNESS

Ordering Information





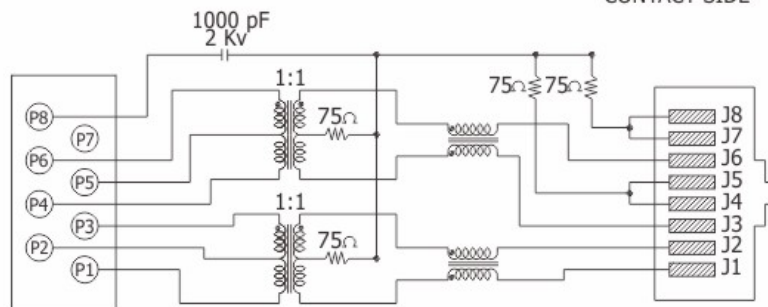
9822 TRANSFORMER TYPE

ELECTRICAL CHARACTERISTICS TEST NOTES: (25°±5°C)

- | | |
|--|---|
| <p>1.TR: (100KHz, 0.1V)
 PINS: (P6-P5-P4):(J6,J3)=1CT:1CT±3%
 PINS: (P3-P2-P1):(J2,J1)=1CT:1CT±3%</p> <p>2.INDUCTANCE: (@0.1V, 100KHz, 8mA, DC Bias)
 PINS: (P6-P4), (P3-P1)=350uH MINIMUM</p> <p>3.DCR:
 PINS: (J6-J3)=(J2-J1)=1.2 OHMS MAXIMUM</p> <p>4.HIPOT:
 PINS(J1,J2)TO(P1,P3)=1500VAC FOR 60 SECONDS
 PINS(J3,J6)TO(P4,P6)=1500VAC FOR 60 SECONDS</p> | <p>5.LEAKAGE INDUCTANCE:
 P6-P4 (WITH J6 AND J3 SPORT)=0.3 MAXIMUM, @1MHz
 P3-P1 (WITH J2 AND J1 SHOR)=0.3 MAXIMUM, @1MHz</p> <p>6.INSERTION LOSS:
 -1.1dB MAXIMUM AT 1MHz TO 100MHz</p> <p>7.RETURN LOSS:
 -18dB MINIMUM AT 1MHz TO 30MHz
 -12dB MINIMUM AT 60MHz TO 80MHz</p> <p>8.CROSS TALK:
 -30dB MINIMUM AT 1MHz TO 100MHz</p> |
|--|---|

CONNECTOR SOLDER SIDE

RJ45
CONTACT SIDE



CONNECTOR SCHEMATIC

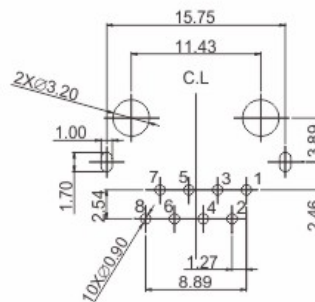
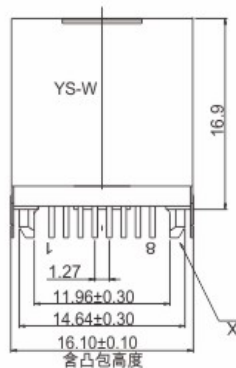
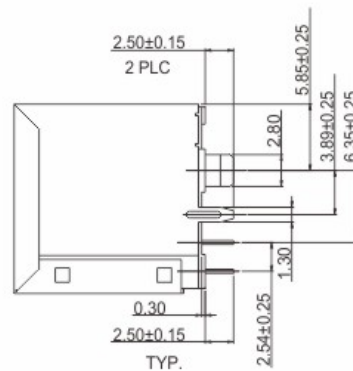
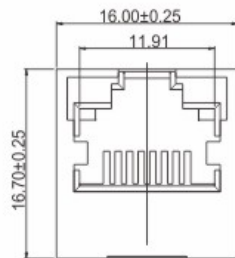
RJ45 10/100 MBPS DIP TYPE



NOTE:

1.MATERIAL:
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
CONTACT: C5191-EH, T=0.35±0.02
SOLDER TAIL: C2680, T=0.35±0.02
SHELL: SUS 201, T=0.20±0.02
2.PLATING:
CONTACT: 30µ"Min Au over
50µ"Min Nickel
Solder AREA: 120µ"Min Tin over

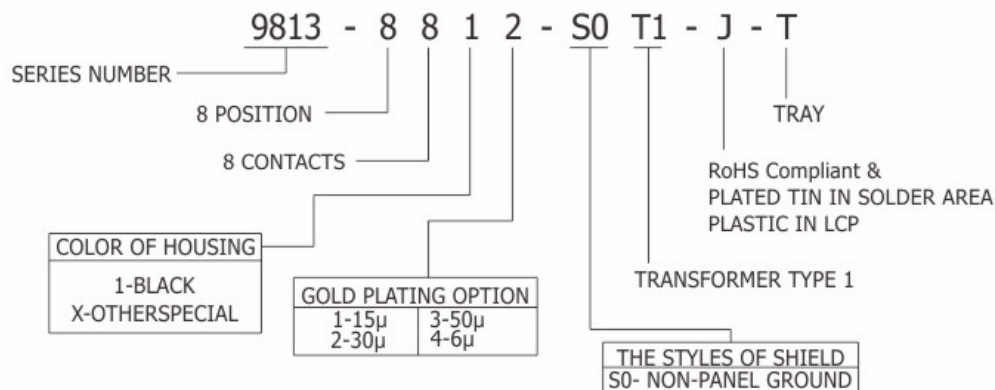
50µ"Min Nickel
SHELL: 20µ"Min Nickel
3.ELECTRICAL
VORAGE RATING: 150
VAC(R.M.S.)MAX
CURRENT RATING: 1.0 AMPERE MAX
INSULATION RESESTANCE: 500 MEGAOHMS MIN
CONTACT RESESTANCE: 40 MILLIOHMS MAXIMUM INITIAL
Storage Temperature: -20°C ~ 85°C



PCB Layout

Ref.

Ordering Information





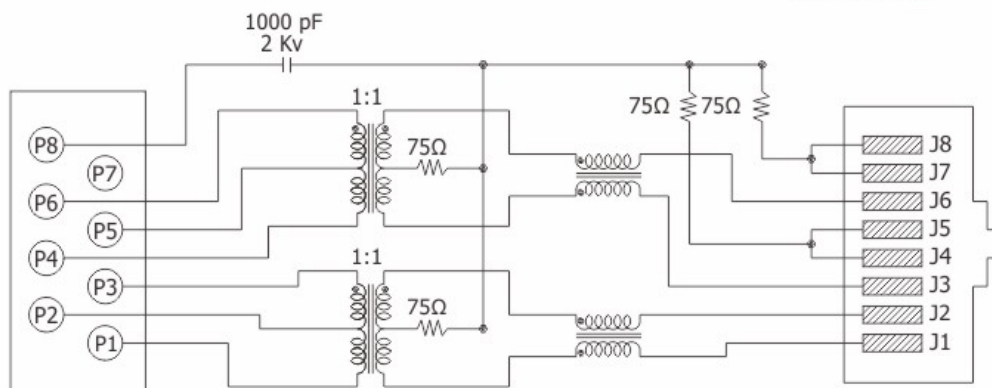
9813 TRANSFORMER TYPE

ELECTRICAL CHARACTERISTICS TEST NOTES: (25°±5°C)

- | | |
|---|--|
| <p>1. TR: (100KHz, 0.1V)
PINS:(P6-P5-P4):(J6,J3)=1CT:1CT±3
PINS:(P3-P2-P1):(J2,J1)=1CT:1CT±3</p> <p>2. INDUCTANCE: (@0.1V, 100KHz, 8mA, DC Bias)
PINS: (P6-P4),(P3-P1)=350uH MINIMUM</p> <p>3. DCR:
PINS: (J6-J3)=(J2-J1)=1.2 OHMS MAXIMUM</p> <p>4. HIPOT:
PINS(J1,J2)TO(P1,P3)=1500VAC FOR 60 SECONDS
PINS(J3,J6)TO(P4,P6)=1500VAC FOR 60 SECONDS</p> <p>5. LEAKAGE INDUCTANCE:
P6-P4 (WITH J6 AND J3 SHOR)=0.3 MAXIMUM, @1MHz
P3-P1 (WITH J2 AND J1 SHOR)=0.3 MAXIMUM, @1MHz</p> | <p>6. INSERTION LOSS:
-1.1dB MAXIMUM AT 1MHz TO 100MHz</p> <p>7. RETURN LOSS:
-18dB MINIMUM AT 1MHz TO 30MHz
-12dB MINIMUM AT 60MHz TO 80MHz</p> <p>8. CROSS TALK:
-30dB MINIMUM AT 1MHz TO 100MHz</p> <p>9. COMMON TO COMMON MODE ATTENUATION:
-35dB MINIMUM AT 30MHz TO 100MHz</p> <p>10. RISE TIME: RS=100 OHMS AND RL=100 OHMS
OUTPUT VOLTAGE=1 V PEAK=3.0 nS MAXIMUM
PULSE WIDTH=112 nS=3.0 nS MAXIMUM</p> <p>11. INTERWINDING CAPACITANCE:
(P6,P5,P4)TO(J6,J3)=30pF MAXIMUM, @1MHz
(P3,P2,P1)TO(J2,J1)=30pF MAXIMUM, @1MHz</p> |
|---|--|

CONNECTOR SOLDER SIDE

RJ45 CONTACT SIDE



NOTES: 1.0 PINS WITHOUT ELECTRICAL CONNECTION ARE OMITTED.

CONNECTOR SCHEMATIC

RJ45 1GBPS DIP TYPE



NOTE:

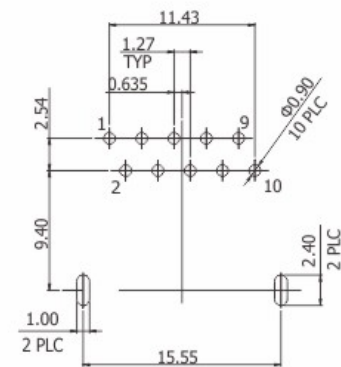
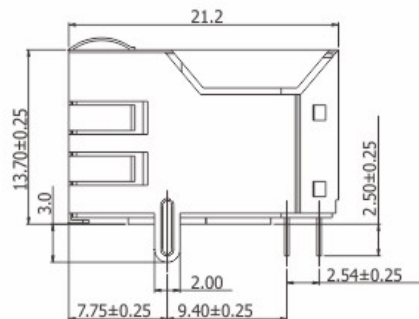
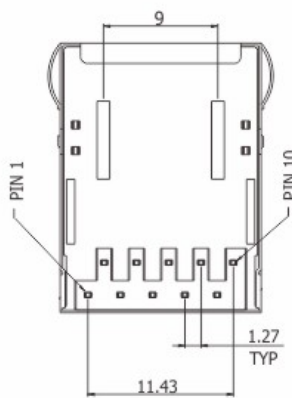
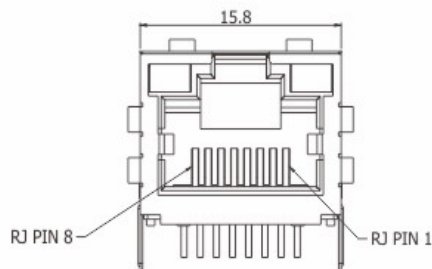
CAVITY CONFIRMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.

1. MATERIAL:

- HOUSING: LCP, UL 94V-0, STANDARD COLOR-BLACK.
- INSERT HOUSING: LCP, UL 94V-0, STANDARD COLOR-BLACK.
- CONTACTS: PHOSPHOR BRONZE.
- SHIELD: BRASS.

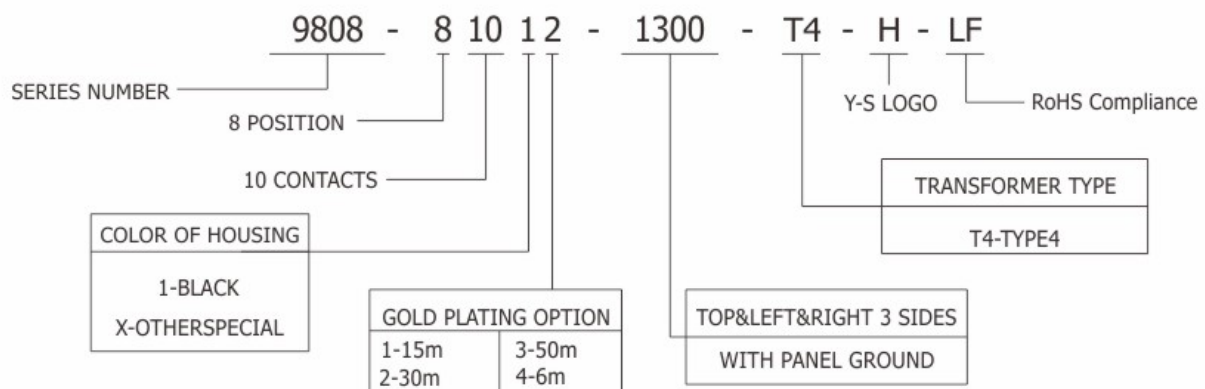
2. FINISH:

- CONTACTS: 0.762mm [30μ"] ON CONTACT AREA,
- 2.032~2.54mm [80 ~ 180μ"] TIN PLATED ON SOLDER TAIL,
- WITH ENTIRE CONTACT UNDERPLATED
- 0.762mm [30μ"] MIN. NICKEL
- LED SOLDER TAIL: 2.54mm [100μ"] MIN. TIN PLATED.
- SHELL: 0.508mm [20μ"] MIN. NICKEL PLATED.



RECOMMENDED PCB LAYOUT
 RECOMMENDED PCB THICKNESS: 1.6mm
 TOLERANCE: ±0.05 (TOP VIEW)

Ordering Information





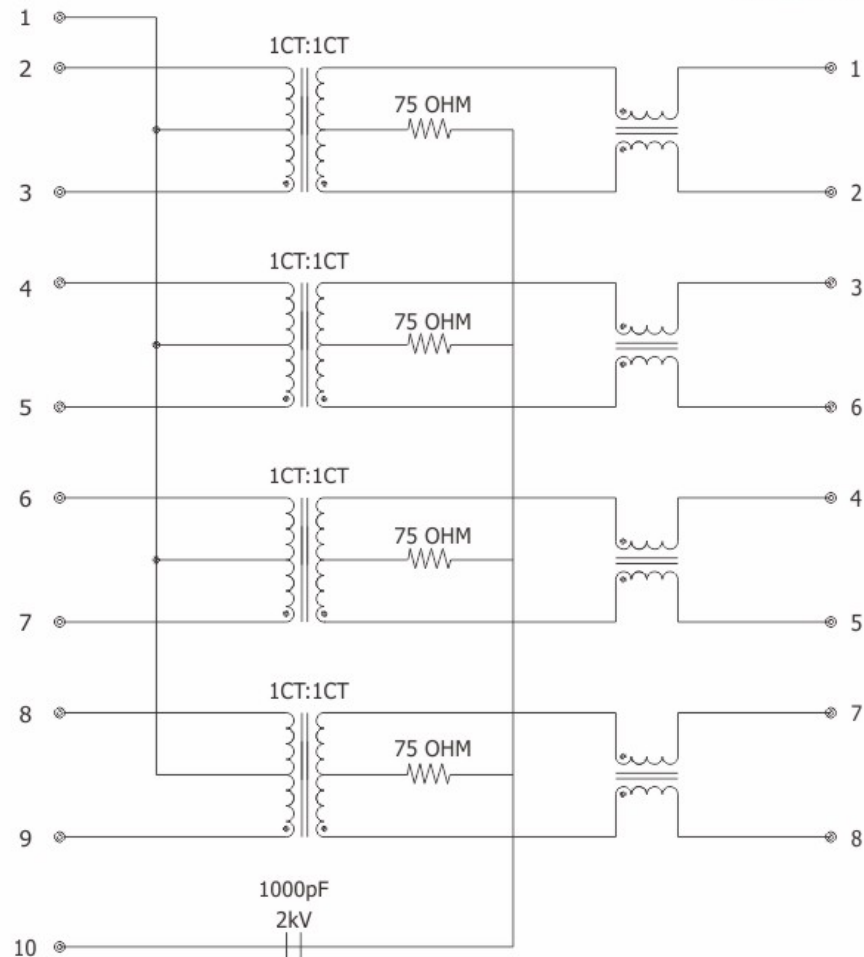
TRANSFORMER TYPE 4

ELECTRICAL CHARACTERISTICS TEST NOTES: (25°±5°C)

- | | |
|--|---|
| 1. OPEN CIRCUIT INDUCTANCE (OCL):
350uH MIN @100kHz, 0.1VRMS.
8mA DC BIAS FROM 0°C TO 70°C | -12dB LOG(f/50)dB MINIMUM FROM 40MHz TO 100MHz |
| 2. INSERTION LOSS:
-1.1dB MAXIMUM AT 1MHz TO 100MHz | 4. CROSS TALK:
-30dB MINIMUM AT 1MHz TO 100MHz |
| 3. RETURN LOSS:
-18dB MINIMUM AT 1MHz TO 40MHz | 5. COMMON TO DIFFERENTIAL MODE REJECTION
-30dB MINIMUM AT 1MHz TO 100MHz |

CONNECTOR SOLDER SIDE

RJ45
CONTACT SIDE



CONNECTOR SCHEMATIC

RJ45 10/100 MBPS DIP TYPE



SPECIFICATIONS:

MATERIAL:

INSULATOR: PA46, RATED UL 94V-0

INSULATOR COLOR: BLACK

CONTACT: PHOSPHOR BRONZE

CONTACT PLATING:

GOLD OVER NICKEL UNDERPLATE

ON CONTACT AREA, TIN OVER

COPPER UNDERPLATE

ON TAILS.

(SEE CHART FOR THICKNESS).

ELECTRICAL:

OPERATING VOLTAGE: 125 VAC
MAX

CURRENT RATING: 15 AMPS MAX

CONTACT RESISTANCE: 30

MOHMS MAX, INITIAL

INSULATION RESISTANCE: 500

MOHMS MIN @ 500 VDC.

DIELECTRIC WITHSTANDING

VOLTAGE: 1500 VAC FOR 1 MINUT.

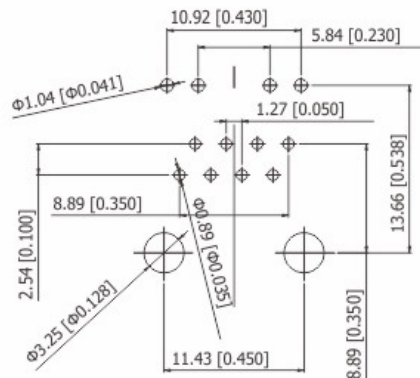
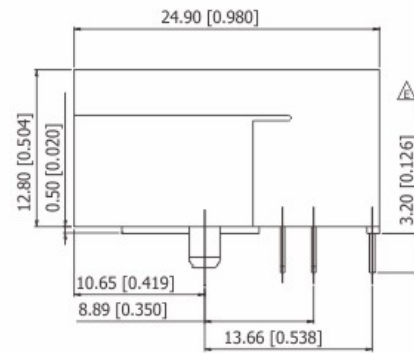
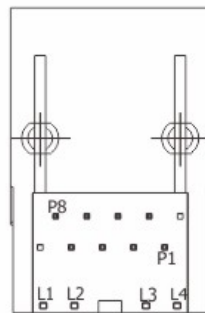
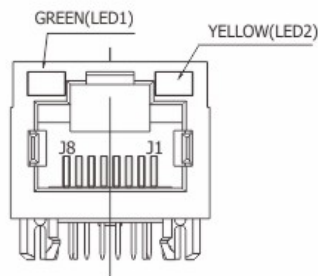
TEMPERATURE RATING:

OPERATING TEMPERATURE: 0°C

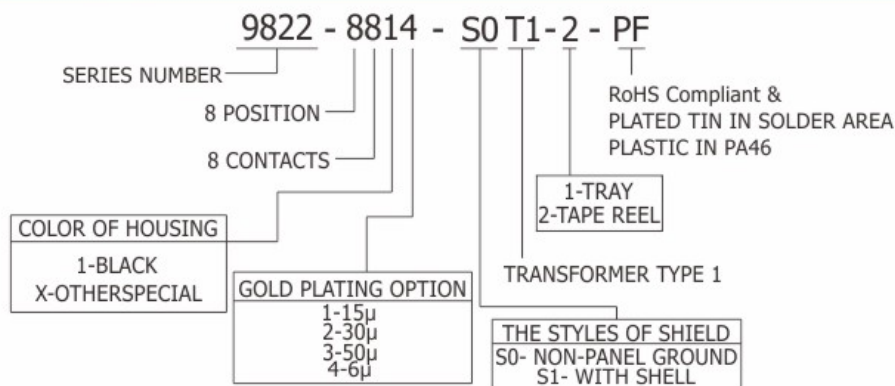
TO +70°C

ENVIRONMENTAL:

LEAD FREE, ROHS COMPLIANT.



Ordering Information



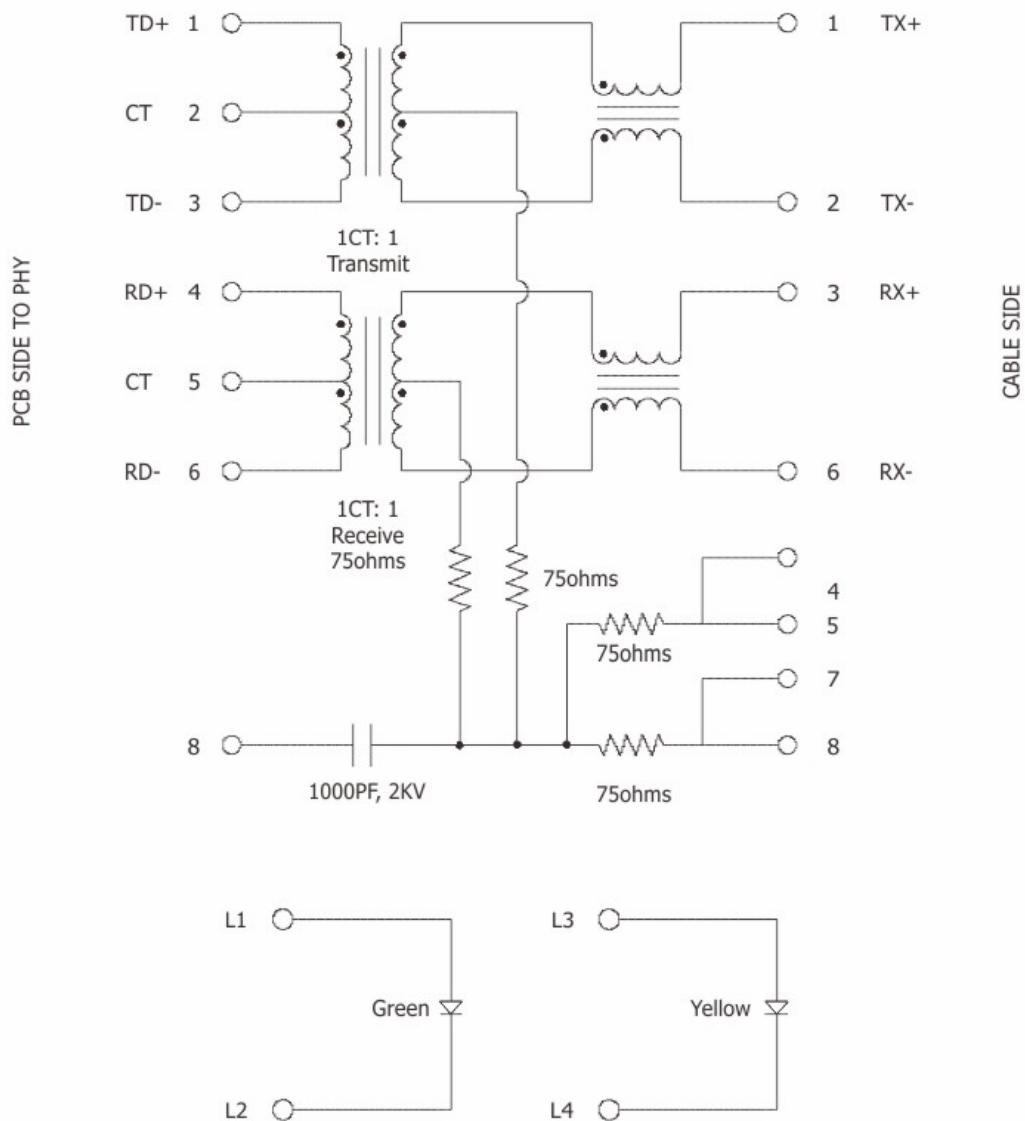


TRANSFORMER TYPE1

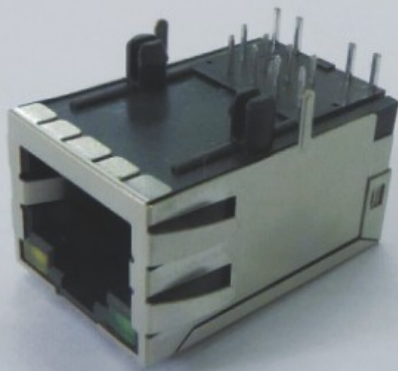
ELECTRICAL SPECIFICATIONS

1. Turns Ratio: TP1-2 1CT: 1CT($\pm 3\%$)
2. Primary Inductance: 350uH min.@0.1V, 100KHZ, 8mADC Bias
3. Hi-POT TEST: TP1-2 1500Vrms
4. TRANSMITTER FILTER
Type: Balance Low Pass 100 Ohm Impedance Nom
Insertion Loss: 0.5 ~ 100MHz 1.0dB MAX

- Return Loss: 0.5 ~ 40MHz 18dB MIN
40 ~ 100MHz 12-20LOG(f/80)dB MIN
5. Cross Talk: 0.5MHZ ~ 40MHZ: 35dB MIN
40MHZ ~ 100MHZ: 33-20LOG(f/50)dB MIN
6. CM to CM REJECTION: 0.5MHZ ~ 100MHZ: 30dB MIN



RJ45 SINKING 10/100 MBPS DIP TYPE



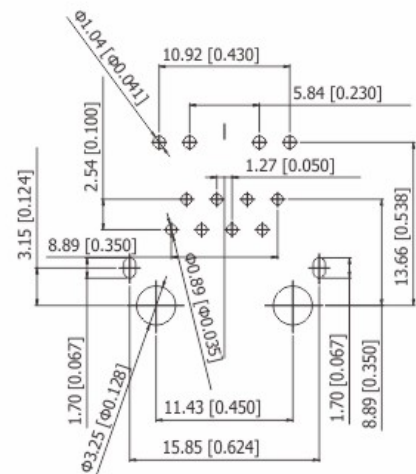
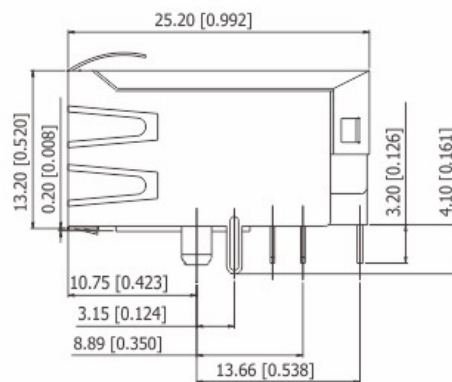
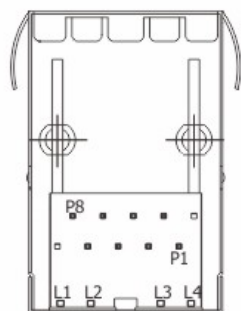
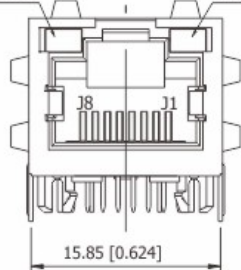
SPECIFICATIONS:

MATERIAL:
 INSULATOR: PA46, RATED UL 94V-0
 INSULATOR COLOR: BLACK
 CONTACT: PHOSPHOR BRONZE
 SHELL: C2680
PLATING:
 TERMINAL: GOLD OVER NICKEL
 UNDERPLATE ON CONTACT
 AREA, TIN OVER COPPER
 UNDERPLATE ON TAILS.
 SHELL: PLATING Ni
ELECTRICAL:
 OPERATING VOLTAGE: 125 VAC

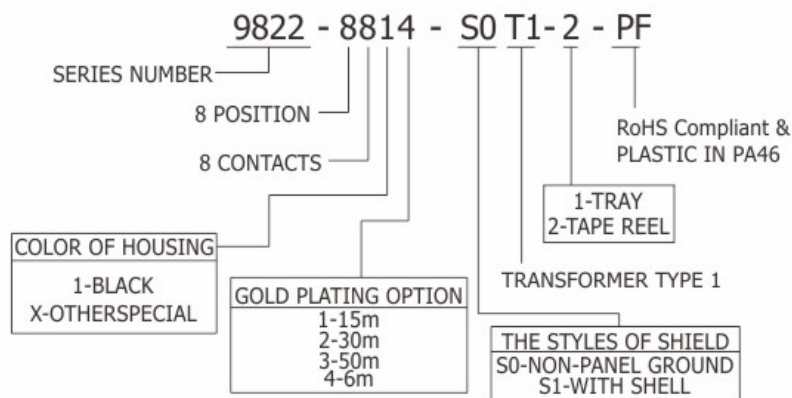
MAX

CURRENT RATING: 15 AMPS MAX
 CONTACT RESISTANCE: 30
 MOHMS MAX, INITIAL
 INSULATION RESISTANCE: 500
 MOHMS MIN @ 500 VDC.
 DIELECTRIC WITHSTANDING
 VOLTAGE: 1500 VAC FOR 1 MINUT.
 TEMPERATURE RATING:
 OPERATING TEMPERATURE: 0°C
 TO +70°C
 ENVIRONMENTAL:
 LEAD FREE, ROHS COMPLIANT.

GREEN(LED1) YELLOW(LED2)



Ordering Information



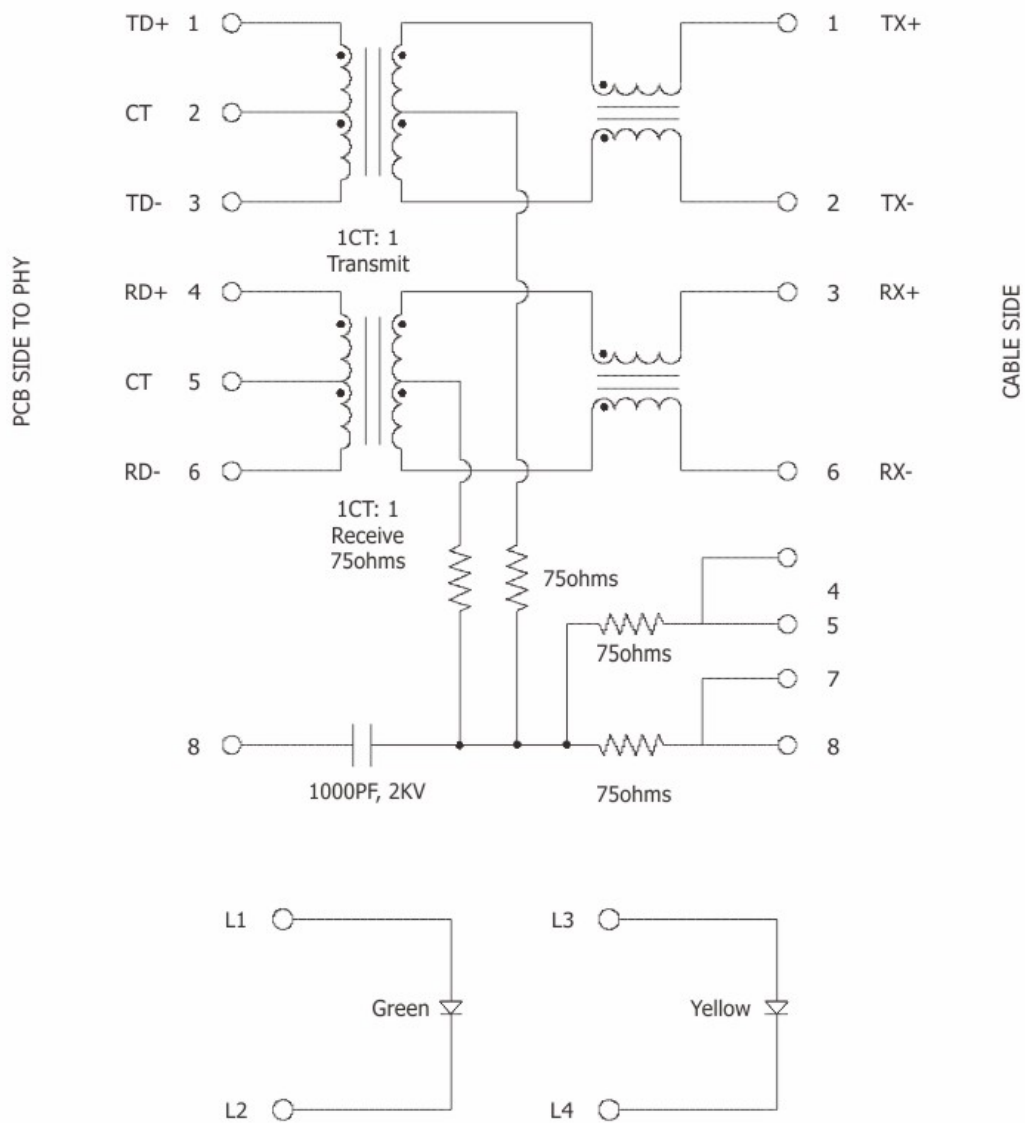


TRANSFORMER TYPE1

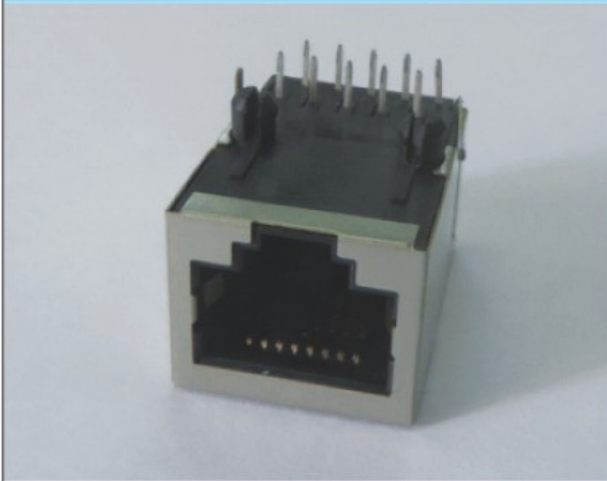
ELECTRICAL SPECIFICATIONS

1. Turns Ratio: TP1-2 1CT: 1CT($\pm 3\%$)
2. Primary Inductance: 350uH min. @0.1V, 100KHZ, 8mADC Bias
3. Hi-POT TEST: TP1-2 1500Vrms
4. TRANSMITTER FILTER
Type: Balance Low Pass 100 Ohm Impedance Nom
Insertion Loss: 0.5 ~ 100MHz 1.0dB MAX

- Return Loss: 0.5 ~ 40MHz 18dB MIN
- 40 ~ 100MHz 12-20LOG(f/80)dB MIN
5. Cross Talk: 0.5MHZ ~ 40MHZ: 35dB MIN
- 40MHZ ~ 100MHZ: 33-20LOG(f/50)dB MIN
6. CM to CM REJECTION: 0.5MHZ ~ 100MHZ: 30dB MIN



RJ45 10/100MBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SOLDER TAIL: SUS 430, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

Solder AREA: 120µ" Min Tin over 50µ" Min Nickel

SHELL: 20µ" Min Ni

3.ELECTRICAL

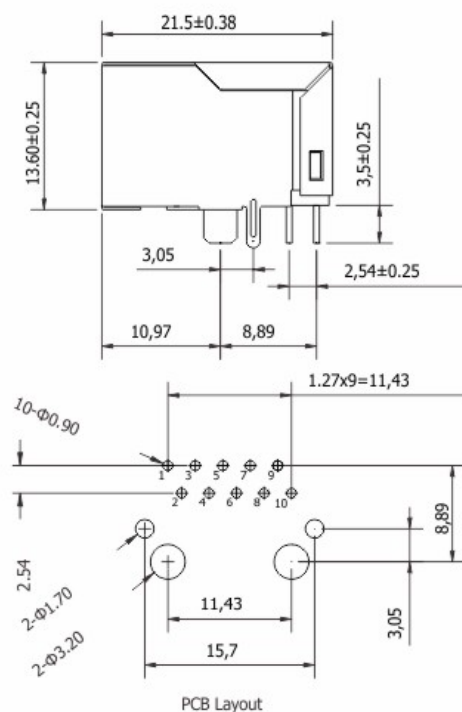
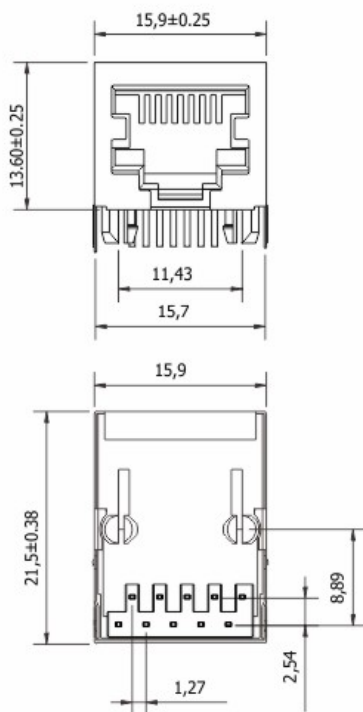
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

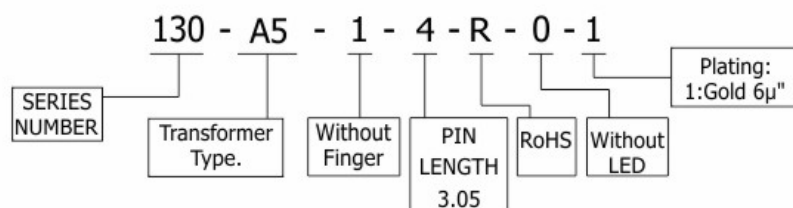
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information



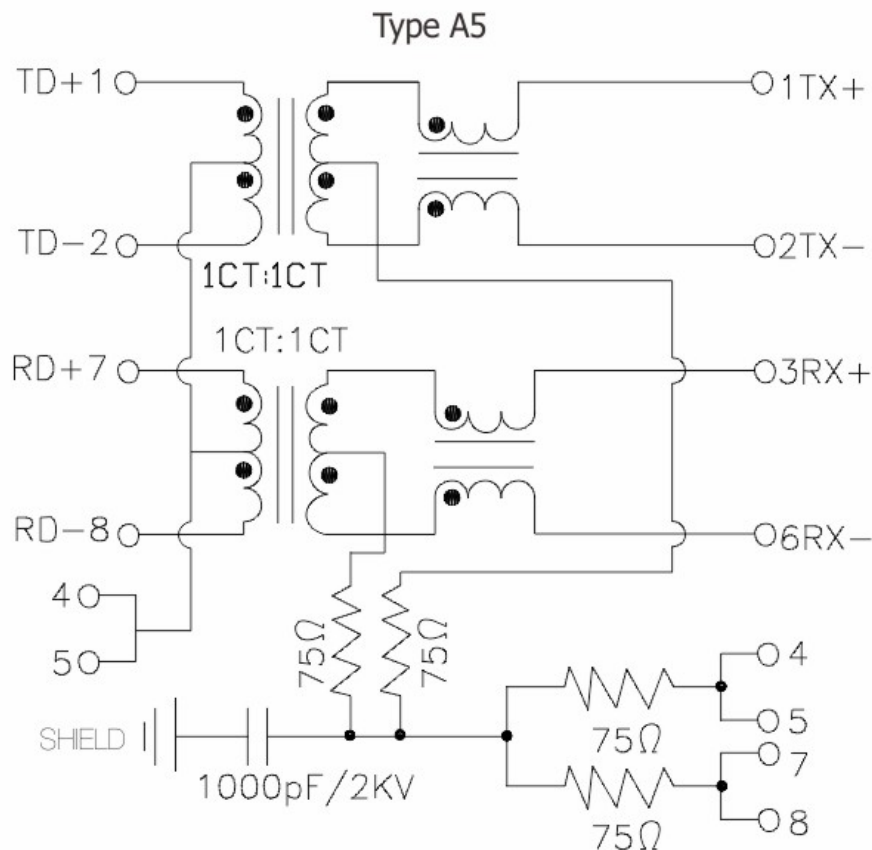


130 TRANSFORMER TYPE

Electrical Specifications @25°C							
Turns Ratio (±2%)		OCL (uH Min.) @100 KHz/0.1V with 8mA DC Bias	Cross talk (dB Min.)				Hi-POT Vrms (VDC) 1.0 mA
TX	RX		0.5-10 MHz	30 MHz	50 MHz	100 MHz	
1CT:1CT	1CT:1CT	350	-50	-40	-35	-30	1500 (2250)

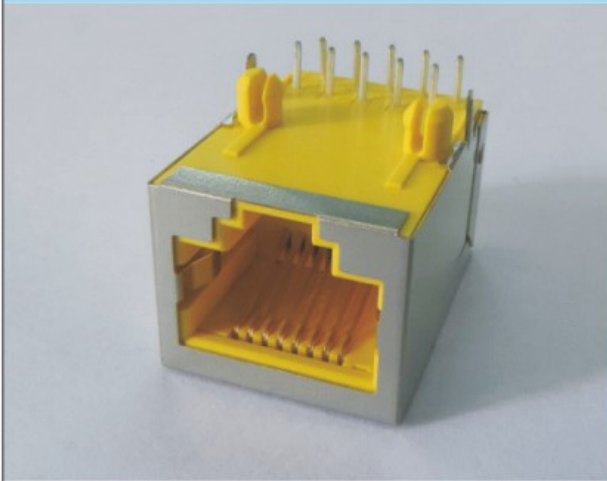
Continue							
Insertion Loss (dB Max.)	Return Loss (dB Min.) @ Load 100 OHM				DCMR (dB Min.)		
1-100 MHz	1-30 MHz	40 MHz	50 MHz	60-80 MHz	1-30 MHz	30-60 MHz	60-100 MHz
-1.0	-19	-16	-14.08	-11.5	-40	-35	-30

Schematic



CONNECTOR SCHEMATIC

RJ45 1GBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5210-EH, T=0.35±0.02

SOLDER TAIL: SUS 430, T=0.35±0.02

SHELL: C2680, T=0.20± 0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

Solder AREA : 120µ" Min Tin over 50µ" Min Nickel

SHELL: 20µ" Min Ni

3.ELECTRICAL

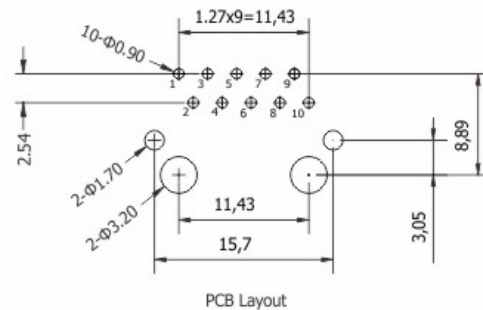
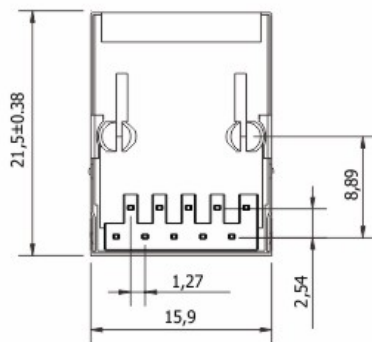
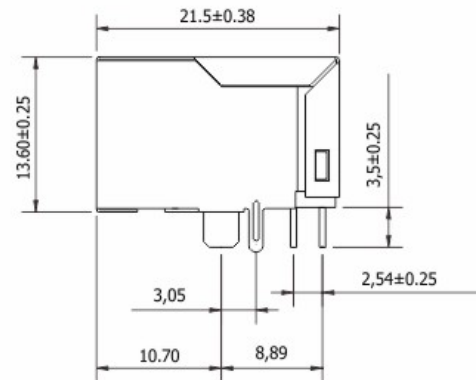
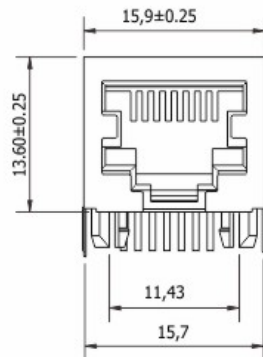
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

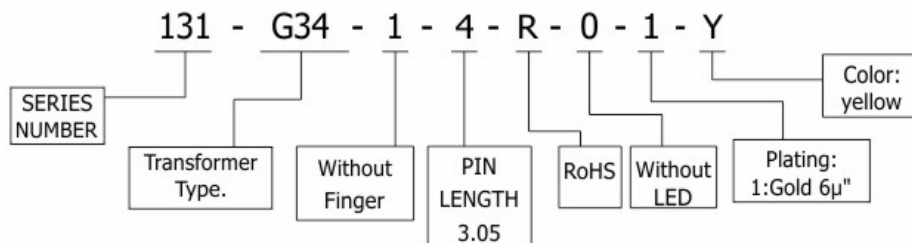
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information





131 TRANSFORMER TYPE

ELECTRICAL SPECIFICATIONS@25°C

Turn Ratio(±2%): 1:1

INSERTION LOSS (1-100MHz): -1.0dB MAX.

Return Loss (dB MIN): -18dB(1-30MHz)

-[18-20LOG(F/30MHz)dB (30-60MHz), -12dB(60-80MHz)

Cross talk (dB MIN): -50dB(0.5-1MHz),-50dB(10MHz)

-40dB (30MHz), -35dB (50MHz), -30dB (100MHz)

CMR(dB MIN): -50dB(0.3-1MHz),-47dB(10MHz)

-42dB (30MHz), -37dB (60MHz), -30dB (100MHz)

CDMR(dB MIN): -50dB(0.3-1MHz),-50dB(10MHz)

-50dB (30MHz), -45dB (60MHz), -40dB (100MHz)

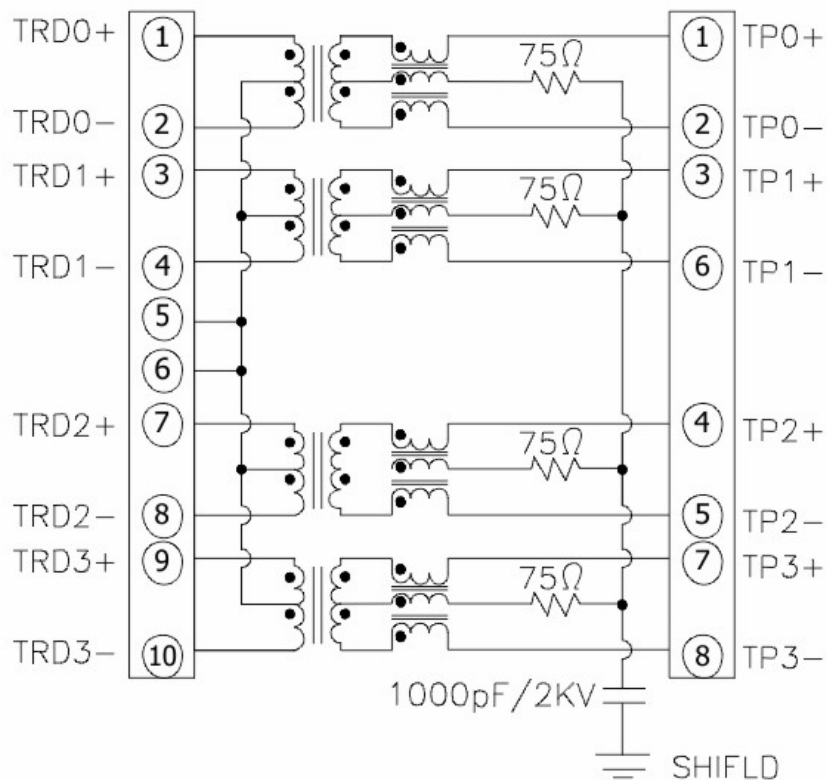
HI-POT TEST: 1500Vrms/0.5mA/2Sec.

PRIMARY INDUCTANCE: 350uH MIN @100KHz/0.1V, 8mA

D.C.BIAS

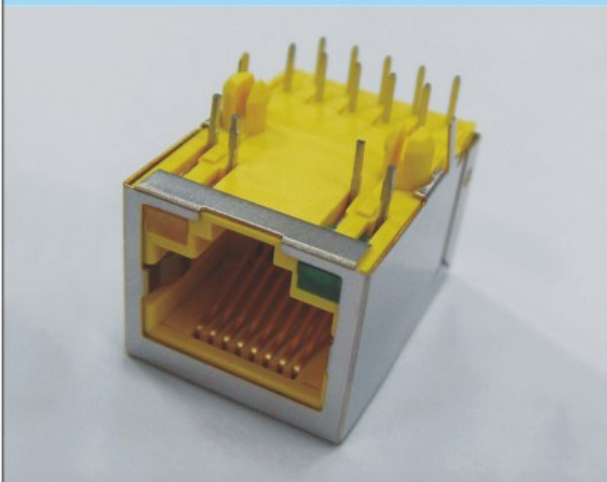
RoHS compliance:YES

Type G34



CONNECTOR SCHEMATIC

RJ45 1GBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5210-EH, T=0.35± 0.02

SOLDER TAIL: SUS 430, T=0.35± 0.02

SHELL: C2680, T=0.20± 0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

Solder AREA : 120µ" Min Tin over 50µ" Min Nickel

SHELL: 20µ" Min Ni

3.ELECTRICAL

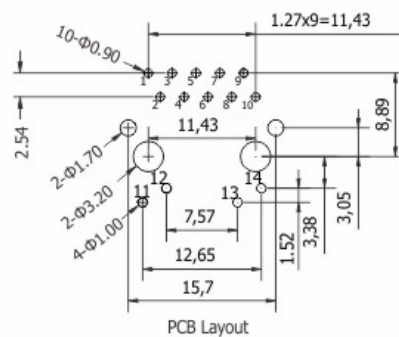
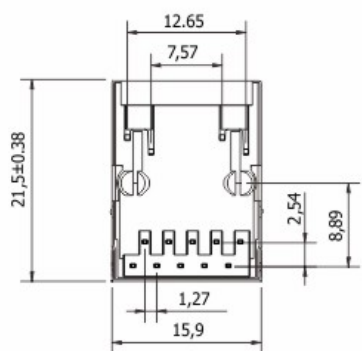
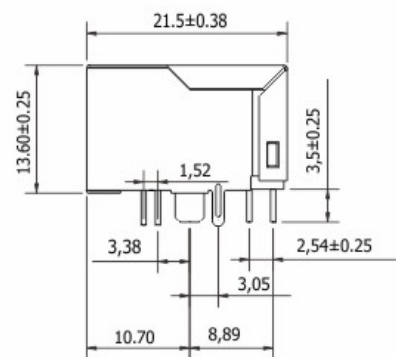
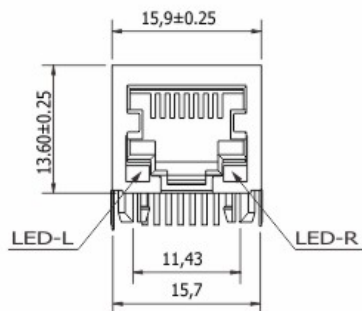
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

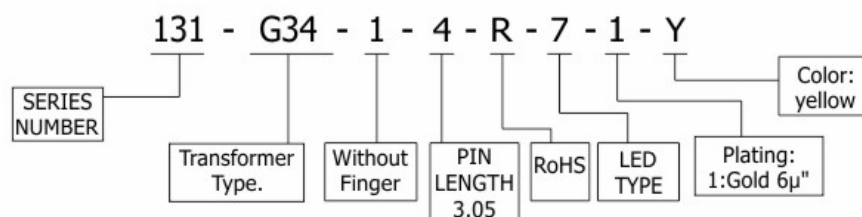
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information





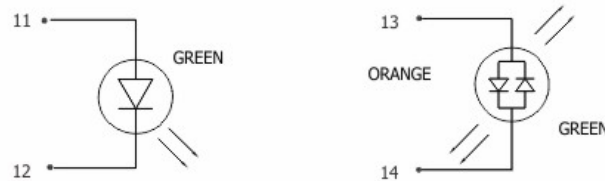
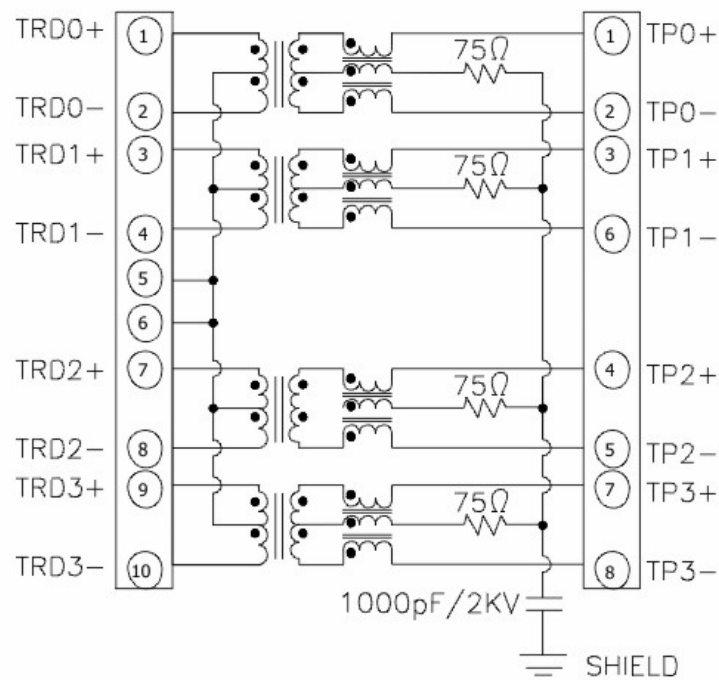
131 TRANSFORMER TYPE

ELECTRICAL SPECIFICATIONS@25°C:

Electrical Specifications @25°C								
Turns Ratio (±2%)		OCL (uH Min.) @100 KHz/0.1V with 8mA DC Bias	Cross talk (dB Min.)				Hi-POT 1.0 mA (V)	
TX	RX		0.5-10 MHz	30 MHz	50 MHz	100 MHz	WITHOUT CAPACITANCE	WITH CAPACITANCE
1CT:1CT	1CT:1CT	350	-50	-40	-35	-30	1500 AC	2250 DC

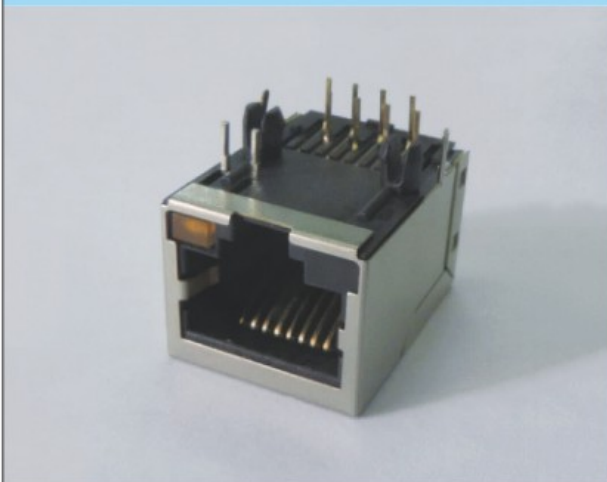
Continue							
Insertion Loss (dB Max.)		Return Loss (dB Min.) @ Load 100 OHM					CMR (dB Min.)
1-100 MHz	100-125 MHz (10/100/1000)	1-30 MHz	30-50 MHz	60 MHz	60-80 MHz	80-100 MHz (10/100/1000)	1-100 MHz
-1.0	-1.2	-18	-16	-14	-12	-10	-30

Type G34



CONNECTOR SCHEMATIC

RJ45 10/100MBPS DIP TYPE



NOTE:

1.MATERIAL:

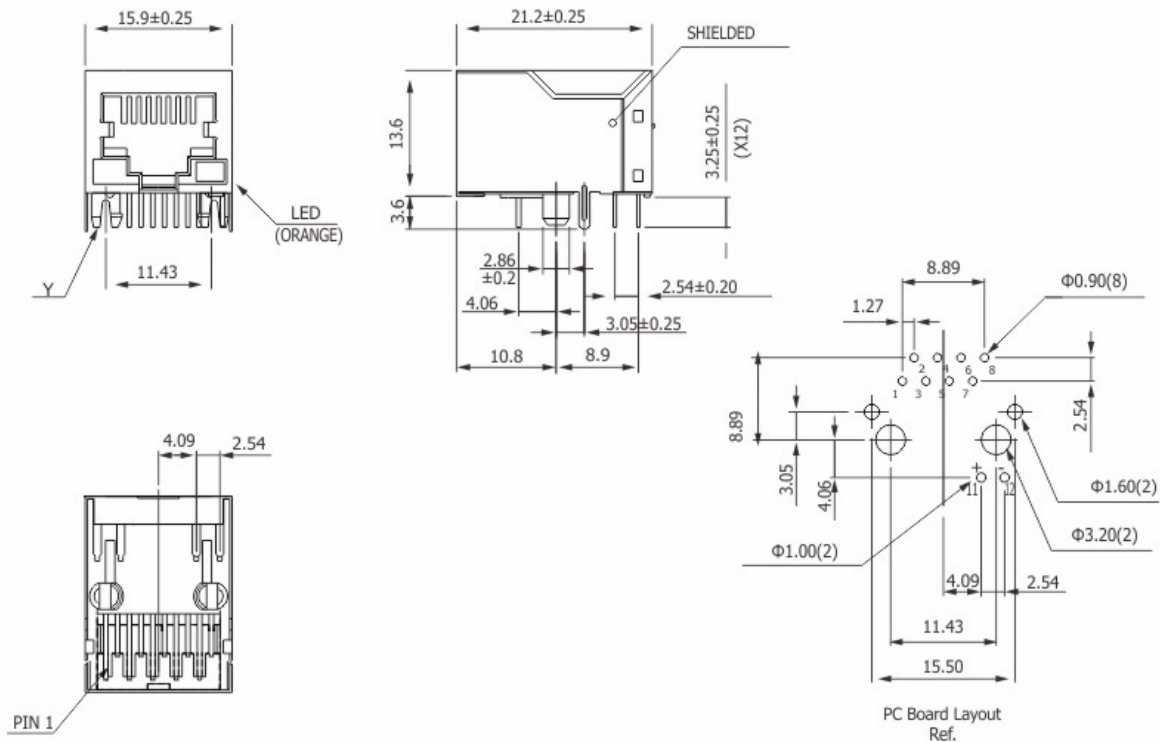
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
 CONTACT: C5191-EH, T=0.35±0.02
 SHELL: C2680, T=0.20±0.02

2.PLATING:

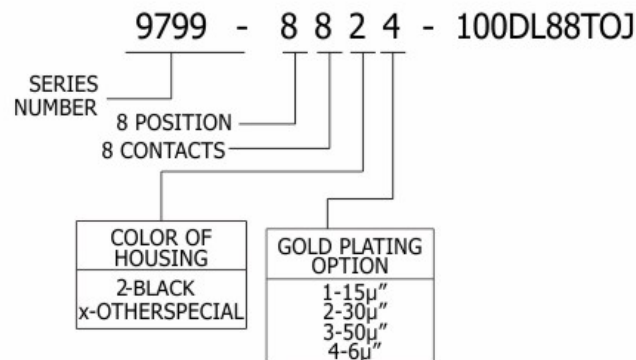
CONTACT: 30μ" Min Au over 50μ" Min Nickel
 SHELL: 20μ" Min Nickel

3.ELECTRICAL

VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS MIN
 CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL
 Storage Temperature: -20°C ~ +85°C



Ordering Information



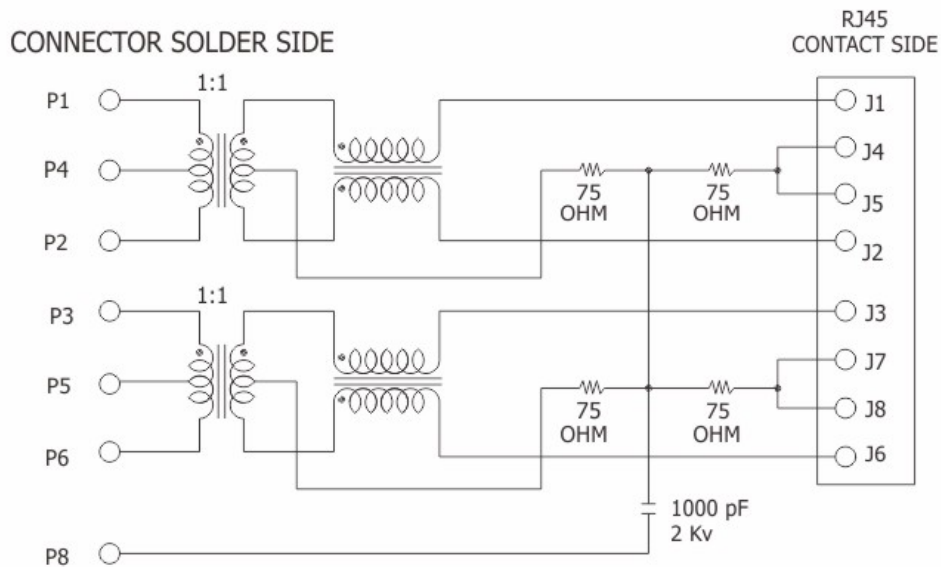


9799 TRANSFORMER TYPE

ELECTRICAL CHARACTERISTICS

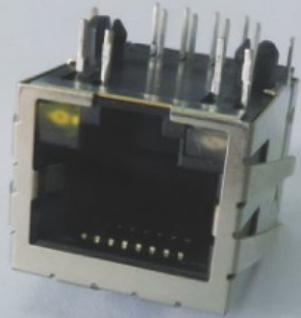
TEST NOTES: (25°±5°C)

Item	Parameter	Condition	Min.	Typ.	Max.	Unit	REMARK
1	Insertion loss	1-100 MHz			-1	dB	
2	Return loss	1-30 MHz	-20			dB	
		30-60 MHz	-15			dB	
		60-80 MHz	-11			dB	
3	Primary Inductance @100KHz, 0.1Vrms, 8mA DC BIAS	(1-2), (3-6)	350			uH	
4	Crosstalk	1-100 MHz	-30			dB	
5	Hipot	Vrms	1.5			kV	



CONNECTOR SCHEMATIC

RJ45 10/100MBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SOLDER TAIL: SUS 430, T=0.35±0.02

SHELL: C2680, T=0.20±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

Solder AREA : 120µ" Min Tin over 50µ" Min Nickel

SHELL: 20µ" Min Nickel

3.ELECTRICAL

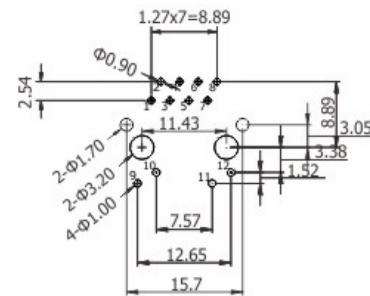
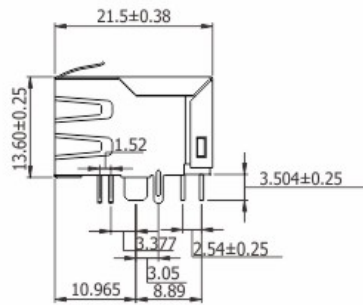
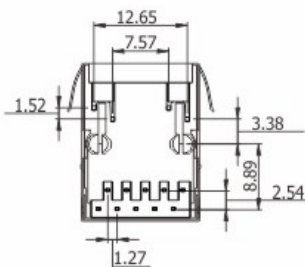
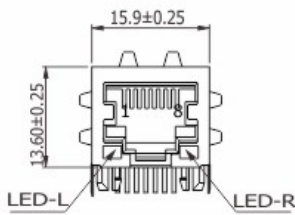
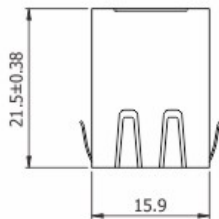
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

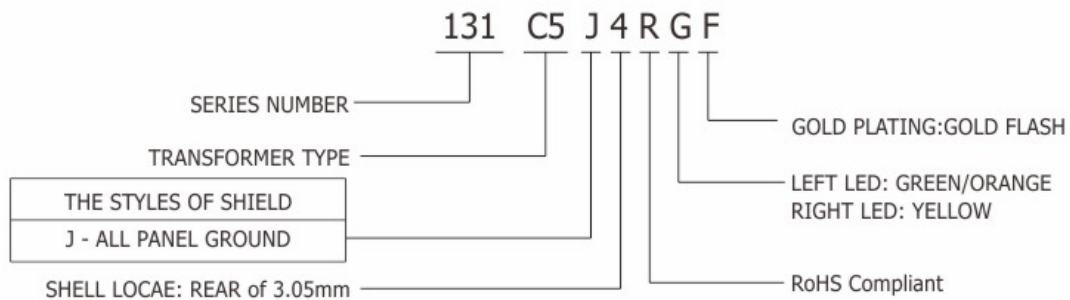
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



RECOMMENDED PCB LAYOUT
TOLERANCE: ±0.05mm (TOP VIEW)

Ordering Information





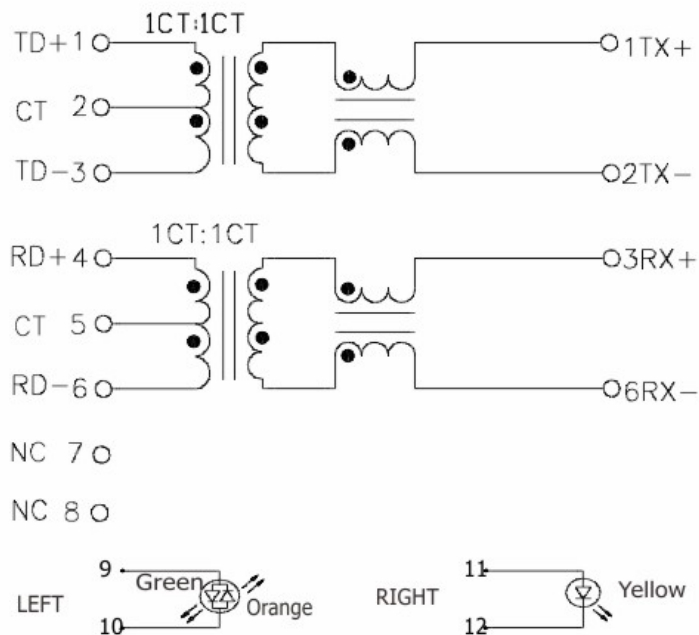
131 TRANSFORMER TYPE

Electrical Specifications @25°C							
Turns Ratio (±2%)		OCL (uH Min.) @100 KHz/0.1V with 8mA DC Bias	Cross talk (dB Min.)				Hi-POT Vrms (VDC) 1.0 mA
TX	RX		0.5-10MHz	30 MHz	50 MHz	100 MHz	
1CT:1CT	1CT:1CT	350	-50	-40	-35	-30	1500 (2250)

Continue							
Insertion Loss (dB Max.)	Return Loss (dB Min.) @ Load 100 OHM				DCMR (dB Min.)		
1-100 MHz	1-30 MHz	40 MHz	50 MHz	60-80 MHz	1-30MHz	30-60MHz	60-100MHz
-1.0	-19	-16	-14.08	-11.5	-40	-35	-30

Schematic

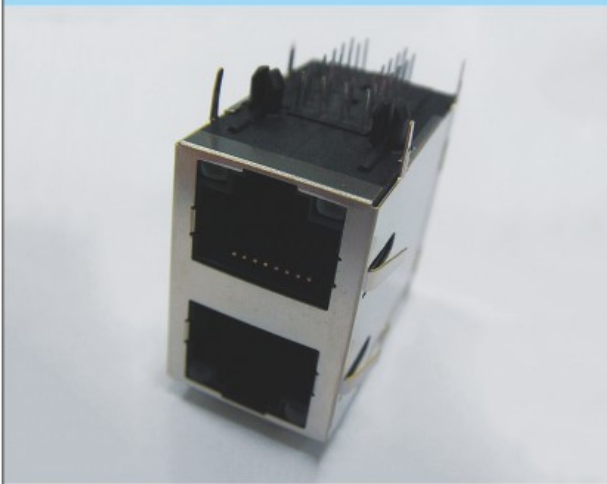
Type C5



Standard LED	Wavelength	Forward*V(MAX)	TYP
Green	565nm	2.5v	2.2v
Yellow	565nm	2.5v	2.1v
Orange	610nm	2.6v	2.1v

WITH A FORWARD CURRENT OF 20mA

RJ45 2*1 PORTS 1GBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SOLDER TAIL: C5191-EH, T=0.35±0.02

SHELL: C2680 H, T=0.20±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

Solder AREA: 120μ" Min Tin over 50μ" Min Nickel

SHELL: 20μ" Min Nickel

3.ELECTRICAL

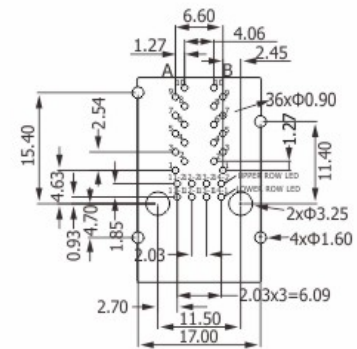
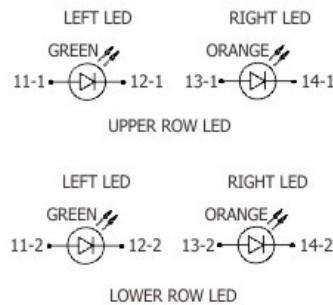
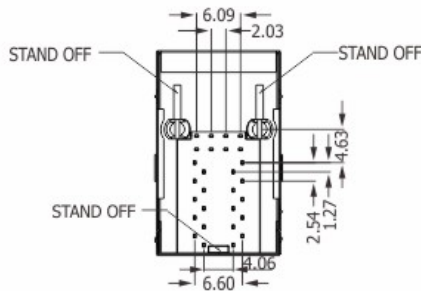
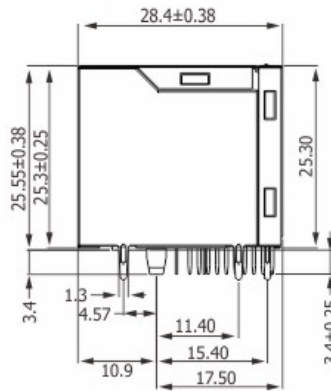
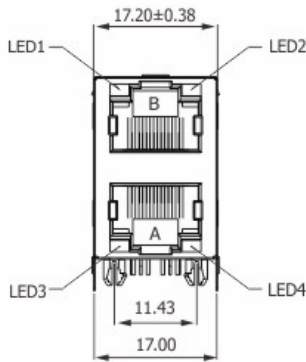
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

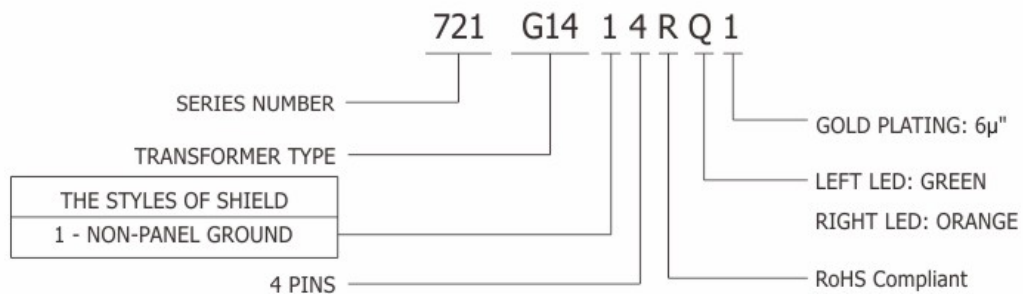
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



RECOMMENDED PCB LAYOUT COMPONENT SIDE
ALL DIMENSION TOLERANCE ARE ±0.05 UNLESS OTHERWISE SPECIFIED

Ordering Information



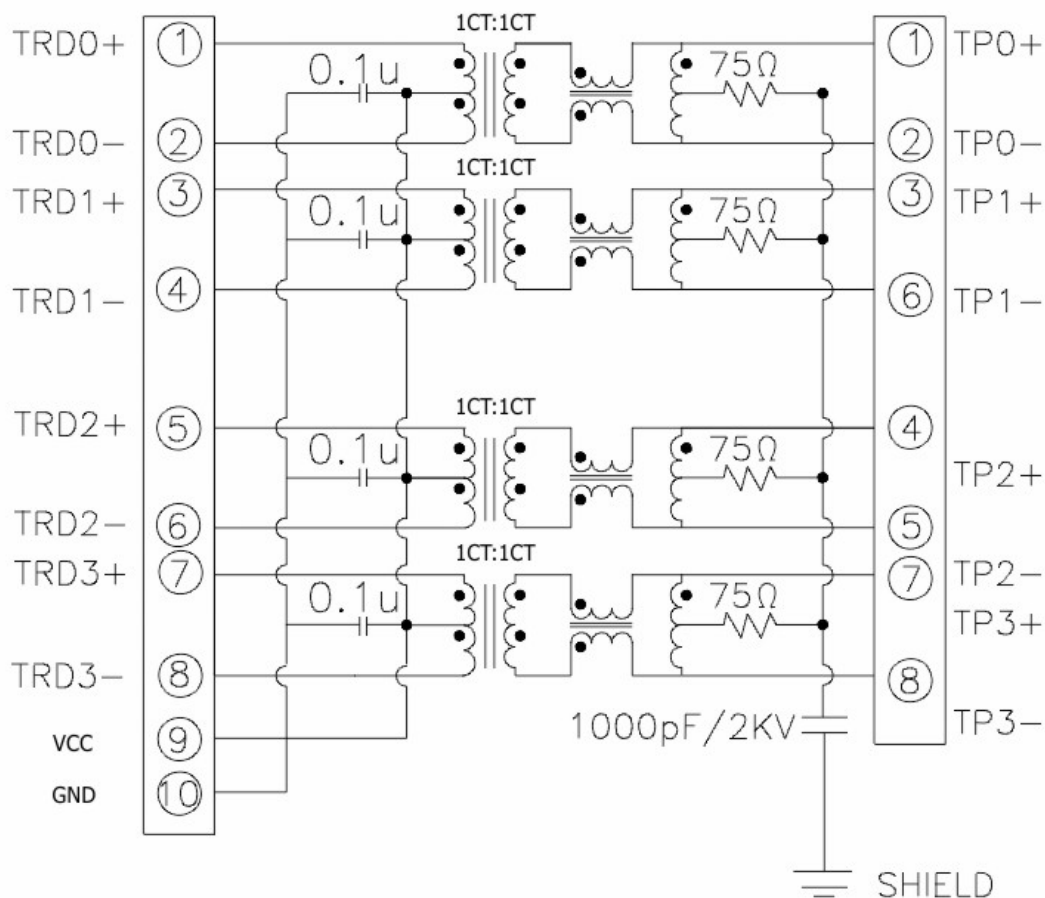


721 TRANSFORMER TYPE

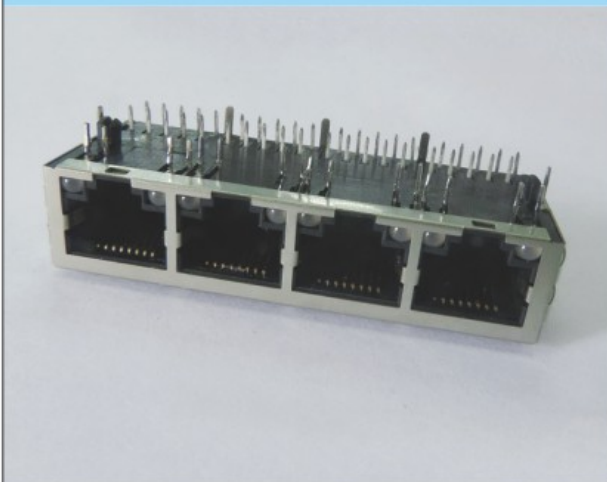
Electrical Specifications @25°C								
Turns Ratio (±2%)		OCL (uH Min.) @100 KHz/0.1V with 8mA DC Bias	Cross talk (dB Min.)				Hi-POT 1.0 mA (V)	
TX	RX		0.5-10 MHz	30 MHz	50 MHz	100 MHz	WITHOUT CAPACITANCE	WITH CAPACITANCE
1CT:1CT	1CT:1CT	350	-50	-40	-35	-30	1500 AC	2250 DC

Continue							
Insertion Loss (dB Max.)		Return Loss (dB Min.) @ Load 100 OHM					CMR (dB Min.)
1-100 MHz	100-125 MHz (10/100/1000)	1-30 MHz	30-50 MHz	60 MHz	60-80 MHz	80-100 MHz (10/100/1000)	1-100 MHz
-1.0	-1.2	-18	-16	-14	-12	-10	-30

Type G14



RJ45 1*4 PORTS 1GBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING:

Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH,

T=0.35±0.02

SOLDER TAIL: SUS 430,

T=0.35±0.02

SHELL:

C2680 H

,T=0.25±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ"

Min Nickel

Solder AREA : 120µ" Min Tin over

50µ" Min Nicke

SHELL: 20µ" Min Ni

3.ELECTRICAL

VOTAGE RATING: 150 VAC

(R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE

MAX

INSULATION RESISTANCE: 500

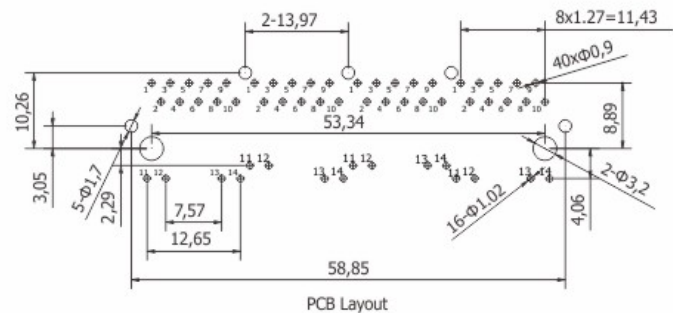
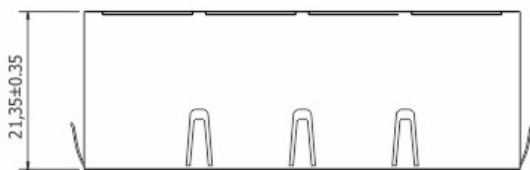
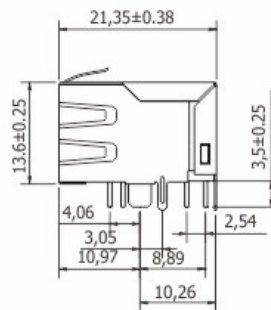
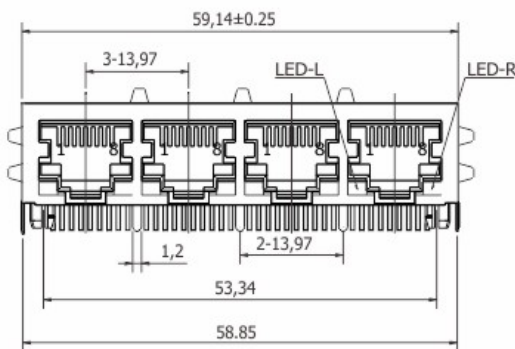
MEGAOHMS MIN

CONTACT RESISTANCE: 40

MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~

+85°C



Ordering Information

134 G2 J 4 R S 3

Series No.

Transformer Type.

With all fingers.

Locate: rear of 3.05

Plating:
3: Gold 30µ"

With LED Type.

Standard operation temp.



134 TRANSFORMER TYPE

ELECTRICAL SPECIFICATIONS@25°C:

Turn Ratio($\pm 2\%$): 1:1

INSERTION LOSS (1-100MHz): -1.0dB MAX.

Return Loss (dB MIN): -18dB(1-30MHz)

-[18-20LOG(F/30MHz)dB (30-60MHz), -12dB(60-80MHz)

Cross talk (dB MIN): -50dB(0.5-1MHz), -50dB(10MHz)

-40dB (30MHz), -35dB (50MHz), -30dB (100MHz)

-40dB (30MHz), -35dB (50MHz), -30dB (100MHz)

-42dB (30MHz), -37dB (60MHz), -30dB (100MHz)

CDMR(dB MIN): -50dB(0.3-1MHz), -50dB(10MHz)

-50dB (30MHz), -45dB (60MHz), -40dB (100MHz)

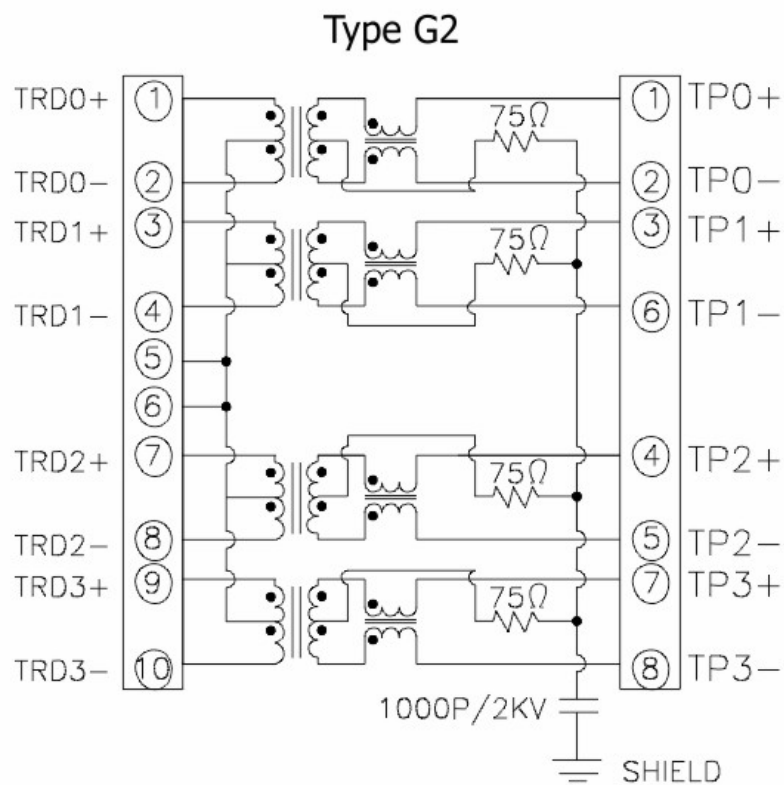
-50dB (30MHz), -45dB (60MHz), -40dB (100MHz)

PRIMARY INDUCTANCE: 350uH MIN @100KHz/0.1V, 8mA

D.C.BIAS

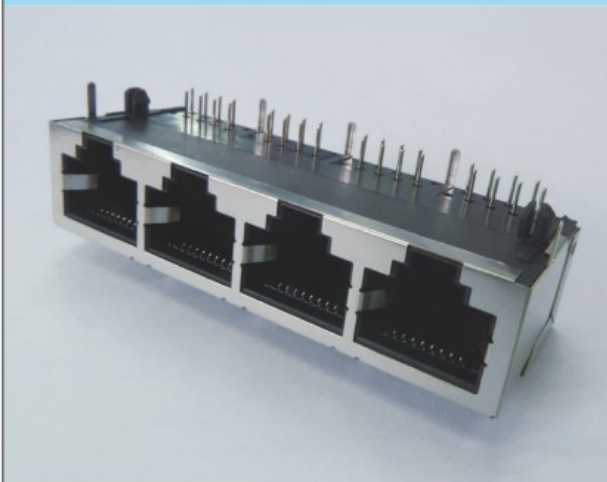
RoHS compliance: YES

Schematic:



CONNECTOR SCHEMATIC

RJ45 1*4 PORTS 10/100MBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH,T=0.35±0.02

SOLDER TAIL: SUS430,T=0.35±0.02

SHELL: C2680,T=0.20±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

Solder AREA: 120μ" Min Tin over 50μ" Min Nickel

SHELL: 20μ" Min Nickel

3.ELECTRICAL

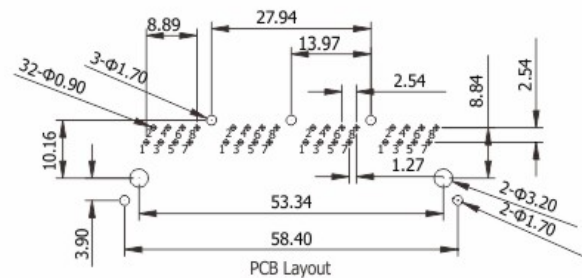
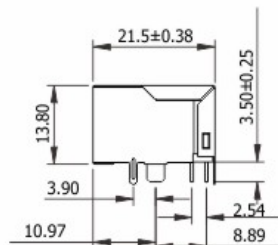
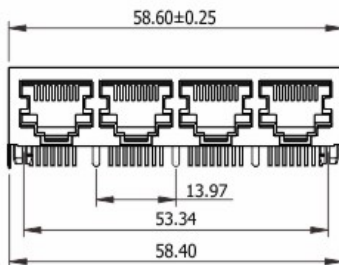
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

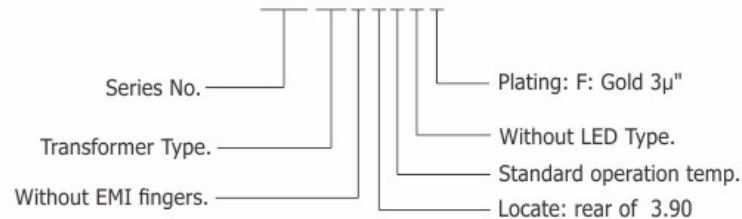
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information

8340313R0F





834 TRANSFORMER TYPE

ELECTRICAL SPECIFICATIONS@25:

Turn Ratio($\pm 2\%$): 1:1

INSERTION LOSS (1-100MHz): -1.0dB MAX.

Return Loss (dB MIN): -18dB(1-30MHz)

-[18-20LOG(F/30MHz)dB (30-60MHz), -12dB(60-80MHz)

Cross talk (dB MIN): -50dB(0.5-1MHz), -50dB(10MHz)

-40dB (30MHz), -35dB (50MHz), -30dB (100MHz)

CMR(dB MIN): -50dB(0.3-1MHz), -47dB(10MHz)

-42dB (30MHz), -37dB (60MHz), -30dB (100MHz)

CDMR(dB MIN): -50dB(0.3-1MHz), -50dB(10MHz)

-50dB (30MHz), -45dB (60MHz), -40dB (100MHz)

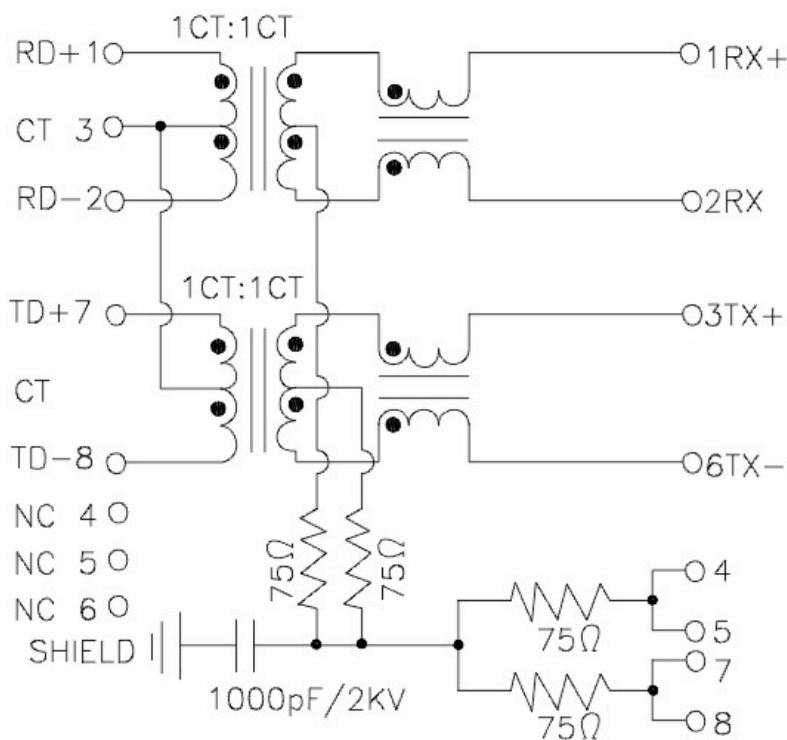
HI-POT TEST: 1500Vrms/1.0mA/3Sec.

PRIMARY INDUCTANCE: 350uH MIN @100KHz/0.1V, 8mAD.C.BIAS

RoHS compliance: YES

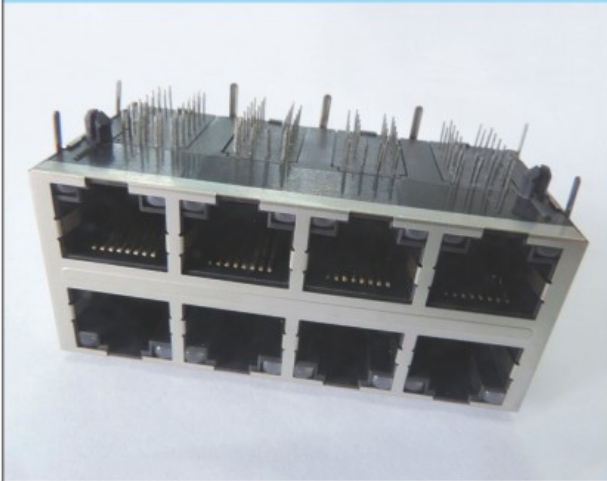
Schematic:

Type 03



CONNECTOR SCHEMATIC

RJ45 2*4 PORTS 1GBPS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5210,T=0.35±0.02

SOLDER TAIL: C2680,T=0.35±0.02

SHELL: C2680, T=0.20±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

Solder AREA: 120μ" Min Tin over 50μ" Min Nickel

SHELL: 20μ" Min Ni

3.ELECTRICAL

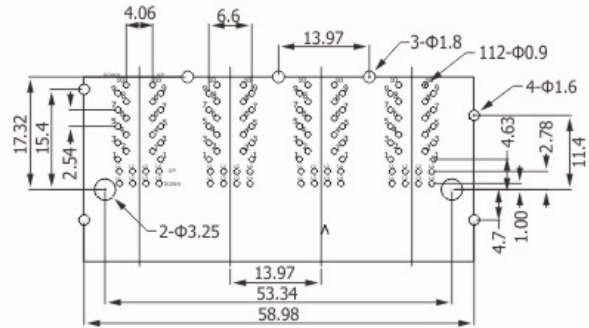
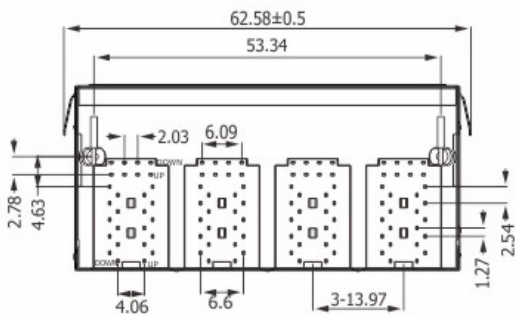
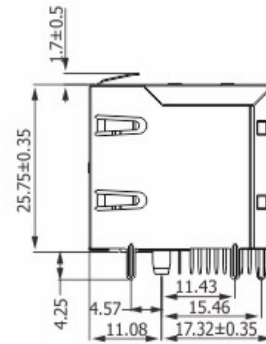
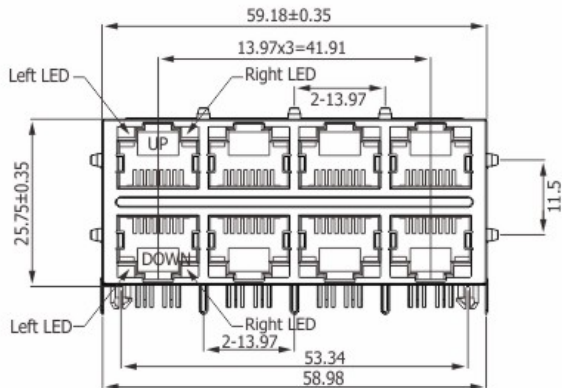
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

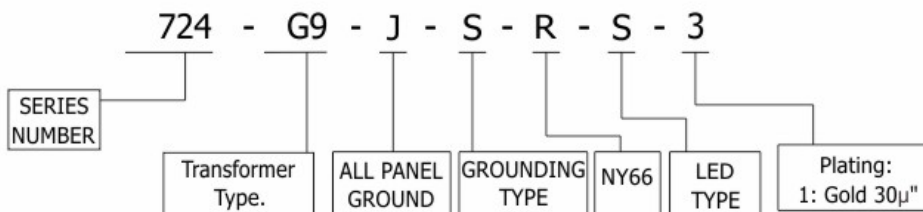
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



RECOMMENDED PCB LAYOUT COMPONENT SIDE
LLDIMFNSION TOLFRANCF ARF ±0.05 UNLFSS OTHFRWISF SPFCIFIFD

Ordering Information





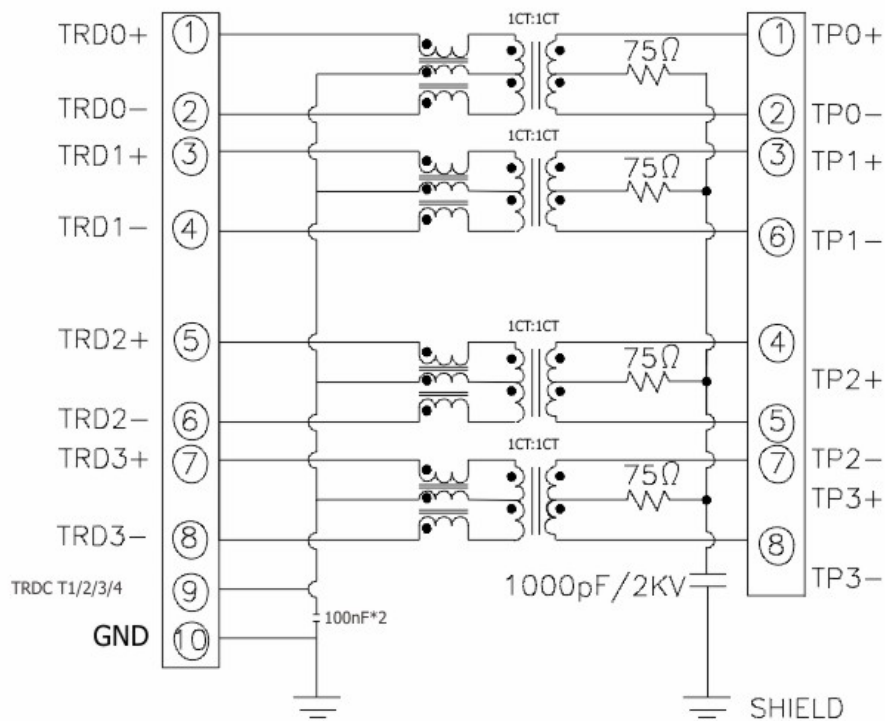
724 TRANSFORMER TYPE

ELECTRICAL SPECIFICATIONS@25°C:

Turn Ratio(±2%): 1:1	-42dB (30MHz), -37dB (60MHz), -30dB (100MHz)
INSERTION LOSS (1-100MHz): -1.0dB MAX.	CDMR(dB MIN): -50dB(0.3-1MHz), -50dB(10MHz)
Return Loss (dB MIN): -18dB(1-30MHz)	-50dB (30MHz), -45dB (60MHz), -40dB (100MHz)
-[18-20LOG(F/30MHz)dB (30-60MHz), -12dB(60-80MHz)	HI-POT TEST: 1500Vrms/0.5mA/2Sec.
Cross talk (dB MIN): -50dB(0.5-1MHz), -50dB(10MHz)	PRIMARY INDUCTANCE: 350uH MIN @100KHz/0.1V, 8mA
-40dB (30MHz), -35dB (50MHz), -30dB (100MHz)	D.C.BIAS
CMR(dB MIN): -50dB(0.3-1MHz), -47dB(10MHz)	RoHS compliance: YES

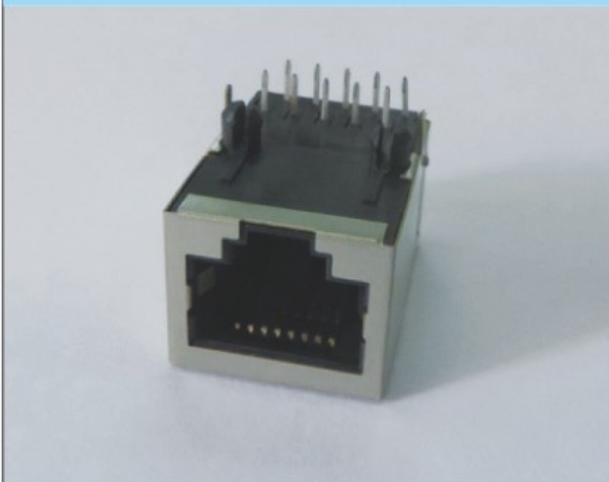
Schematic

Type G9

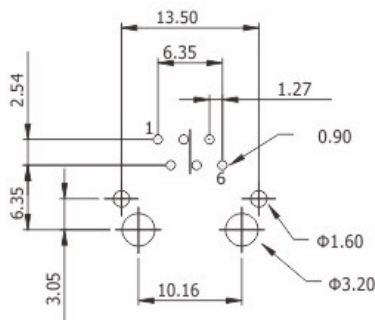
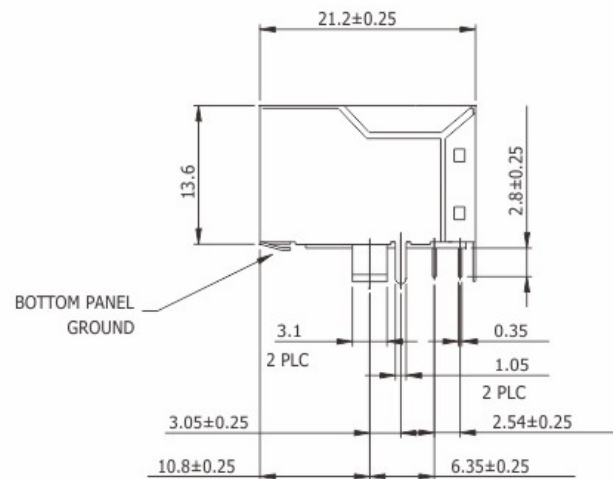
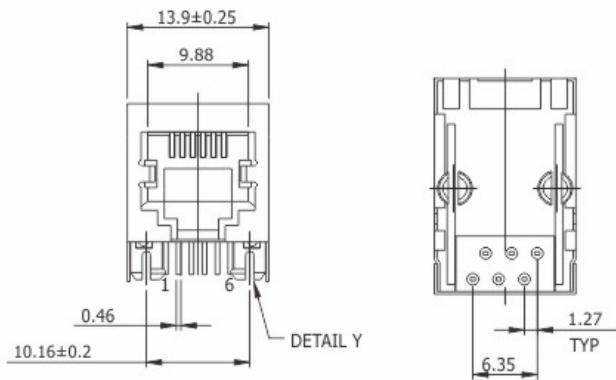


CONNECTOR SCHEMATIC

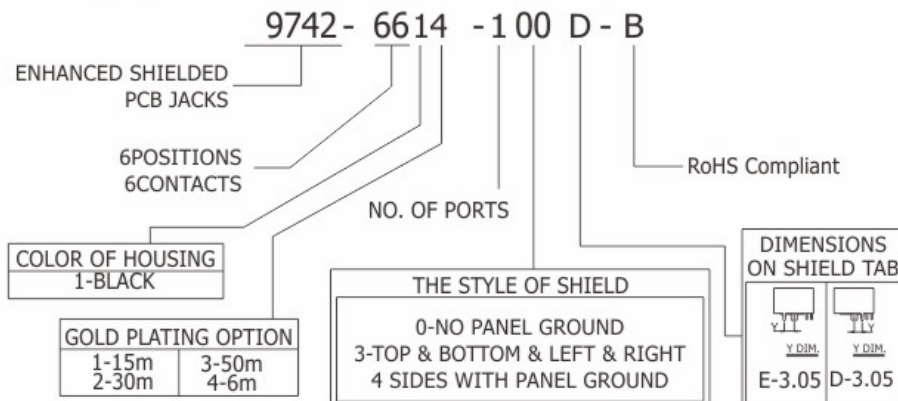
RJ11 DIP TYPE



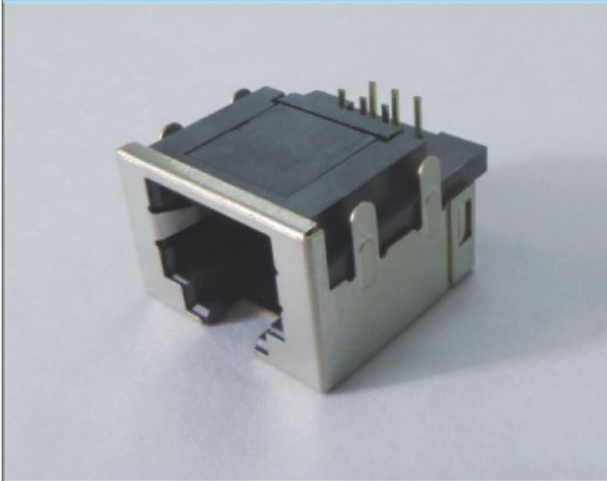
MATERIAL: HOUSING-PBT POLYESTER UL94V-0
 MIXED GLASS FIBER.
 STANDARD COLOR-BLACK
 CONTACTS-0.35mm THICK PHOS-BRONZE
 PLATED WITH HARD GOLD AND
 GOLD FLASH IN SOLDER AREA.
 SHIELD-0.25mm THICK COPPER ALLOY,
 PLATED WITH NICKEL.
 CAVITY CONFIRMS TO FCC RULES AND REGULATIONS
 PART 68,SUBPART F.



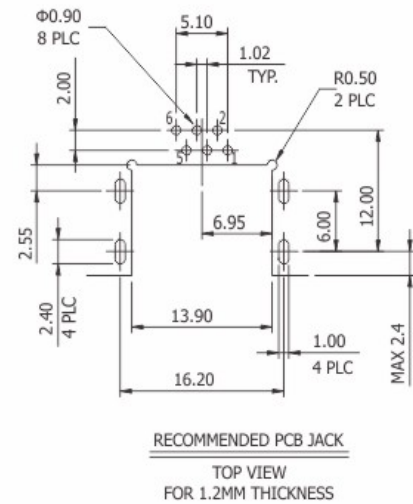
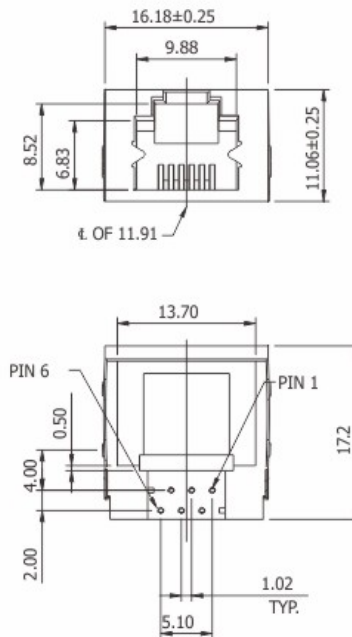
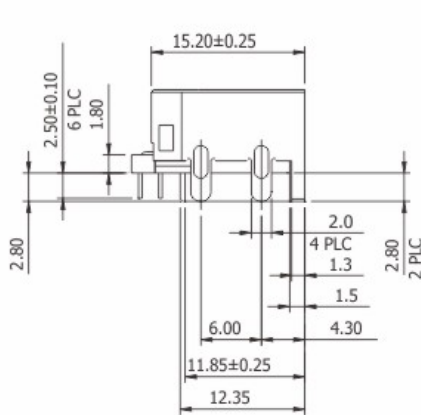
Ordering Information



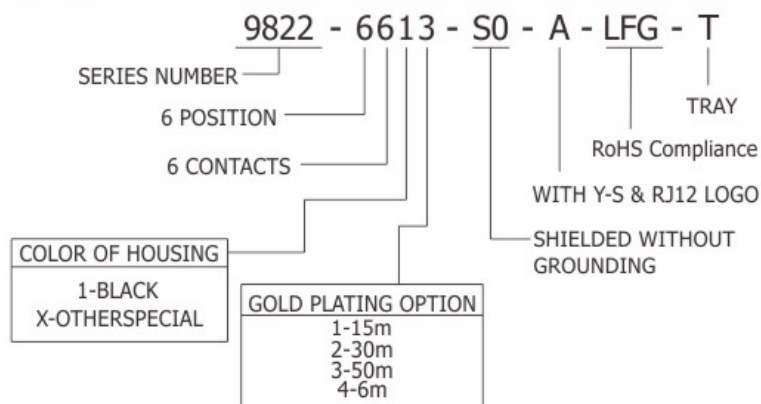
RJ11 SINKING DIP TYPE



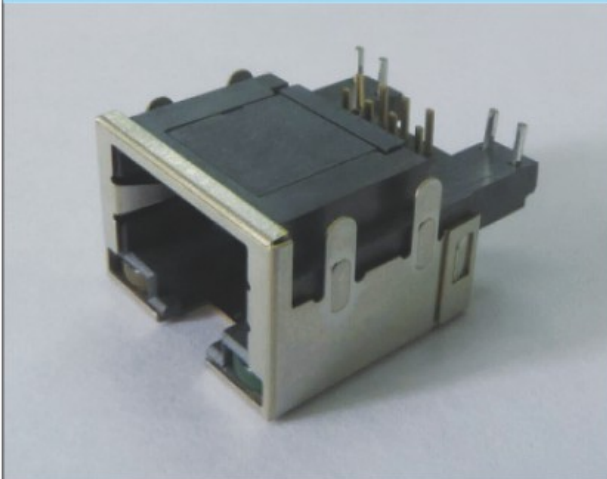
MATERIAL:
 HOUSING-DUPONT ZENITE LCP 6130L UL94V-0
 HEAT DEFLECTION TEMP.265°
 STANDARD COLOR-BLACK
 CONTACTS -0.35mm THICK PHOS-BRONZE PLATED
 WITH HARD GOLD AND GOLD FLASH IN
 SOLDER AREA.
 SHIELD-0.20mm THICK COPPER ALLOY,
 PLATED WITH NICKEL.
 CAVITY CONFIRMS TO FCC RULES AND REGULATIONS
 PART 68,SUBPART F.



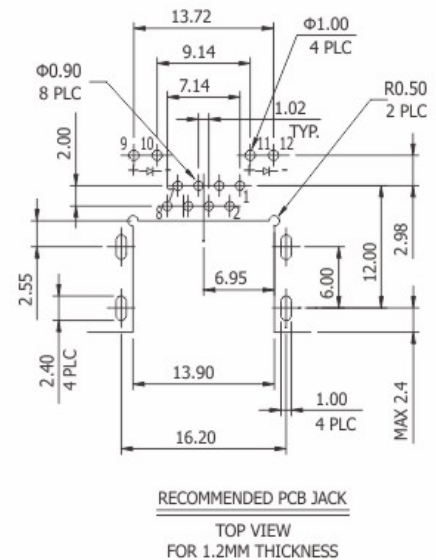
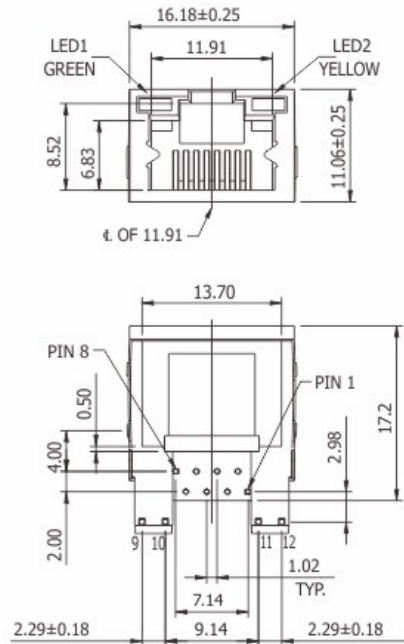
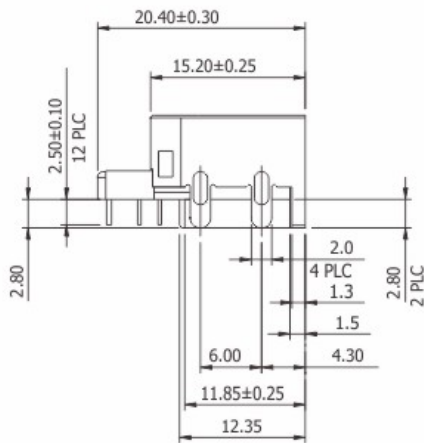
Ordering Information



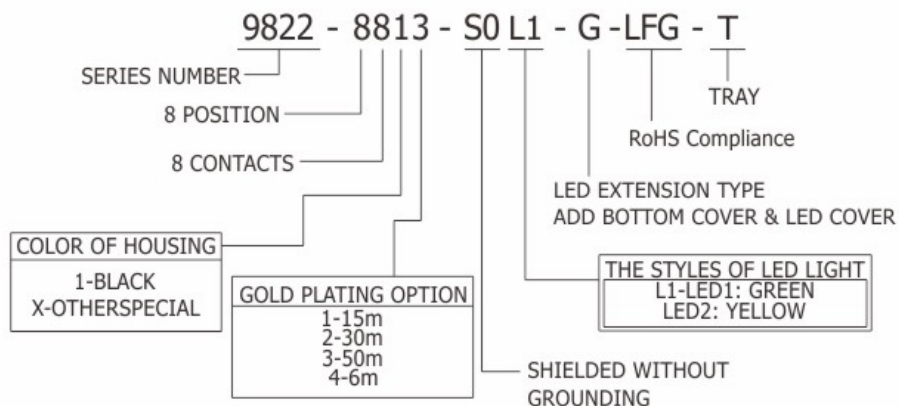
RJ45 SINKING DIP TYPE



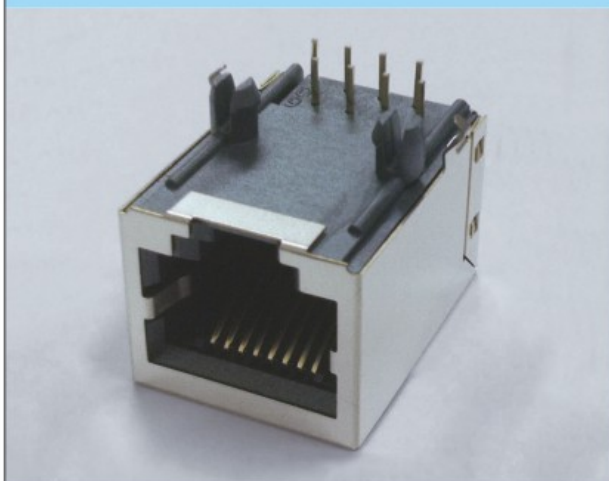
MATERIAL:
 HOUSING-LCP UL94V-0
 HEAT DEFLECTION TEMP.265°
 STANDARD COLOR-BLACK
 CONTACTS -0.35mm THICK PHOS-BRONZE PLATED
 WITH HARD GOLD AND GOLD FLASH IN
 SOLDER AREA.
 SHIELD-0.20mm THICK COPPER ALLOY,
 PLATED WITH NICKEL.
 CAVITY CONFIRMS TO FCC RULES AND REGULATIONS
 PART 68,SUBPART F.



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02
 SOLDER TAIL: C2680, T=0.35±0.02
 SHELL: C2680, T=0.25±0.02

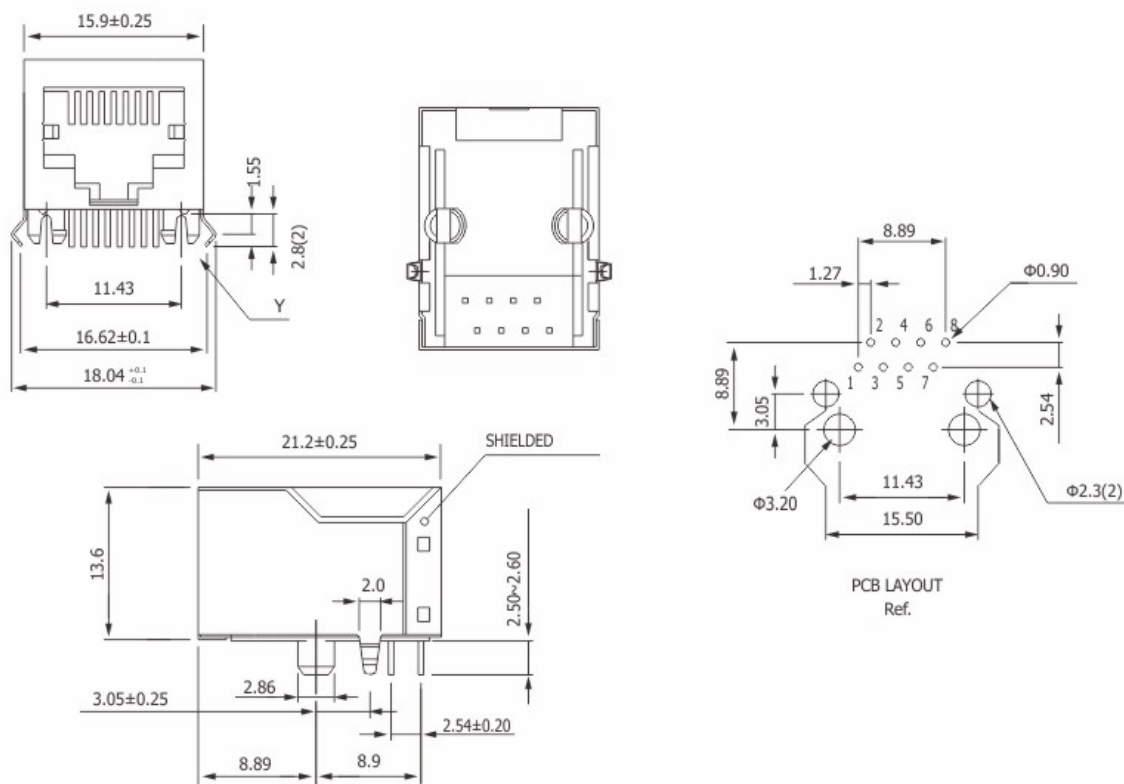
2.PLATING:

CONTACT: 30u"Min Au over 50u"Min Nickel
 Solder AREA: 120u"Min Tin over 50u"Min Nickel

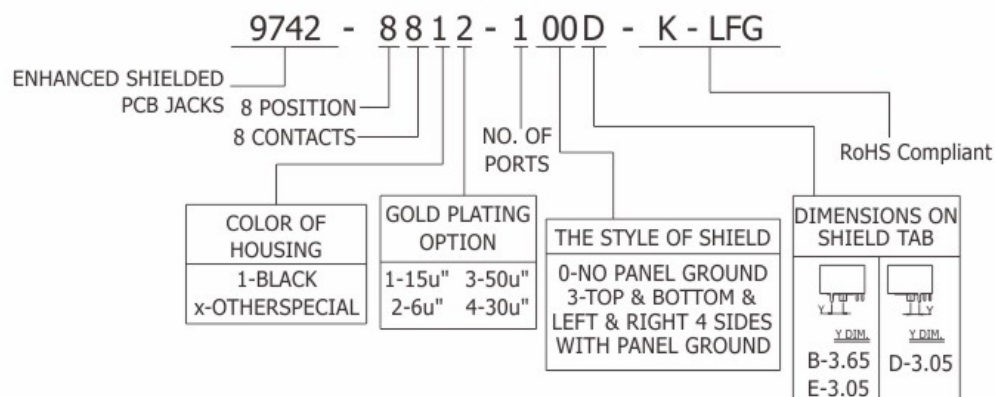
SHELL: 20u"Min Nickel

3.ELECTRICAL

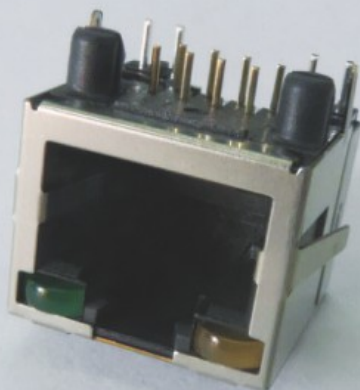
VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS MIN
 CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL DIELECTIC WITHSTANDING VOLTAGE: 1000 VAC AT SEE LEVEL
 Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

SHELL: 20μ" Min Ni

3.ELECTRICAL

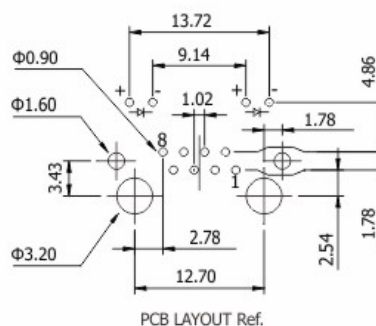
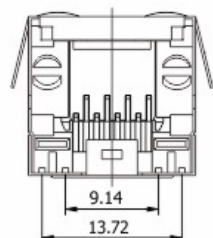
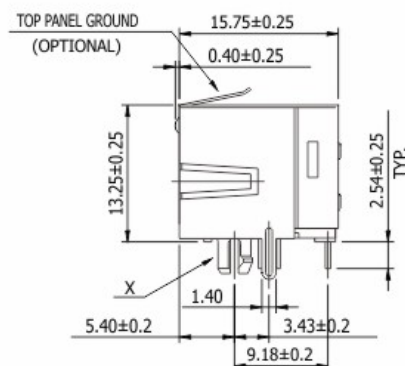
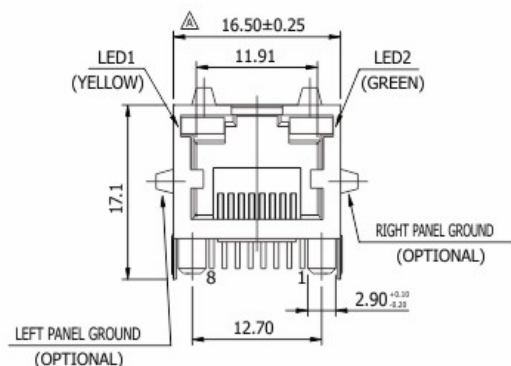
VOTAGE RATING: 150 VAC (R.M.S.) MAX

CURRENT RATING: 1.0 AMPERE MAX

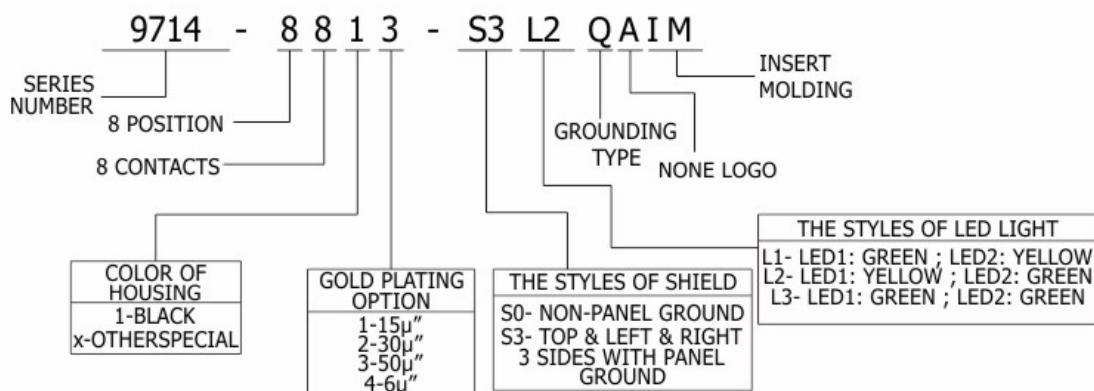
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

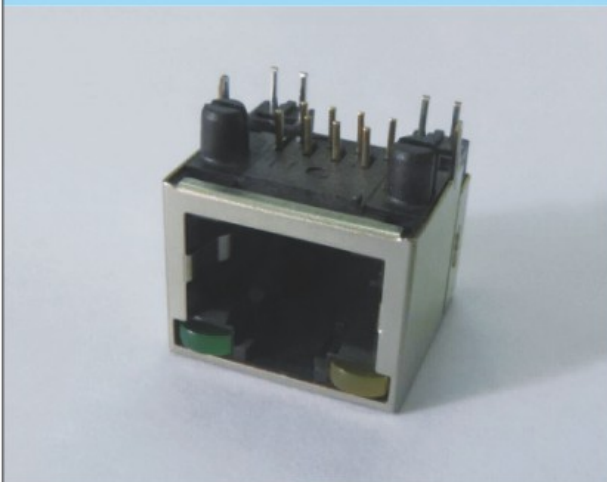
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

SHELL: 20µ" Min Ni

3.ELECTRICAL

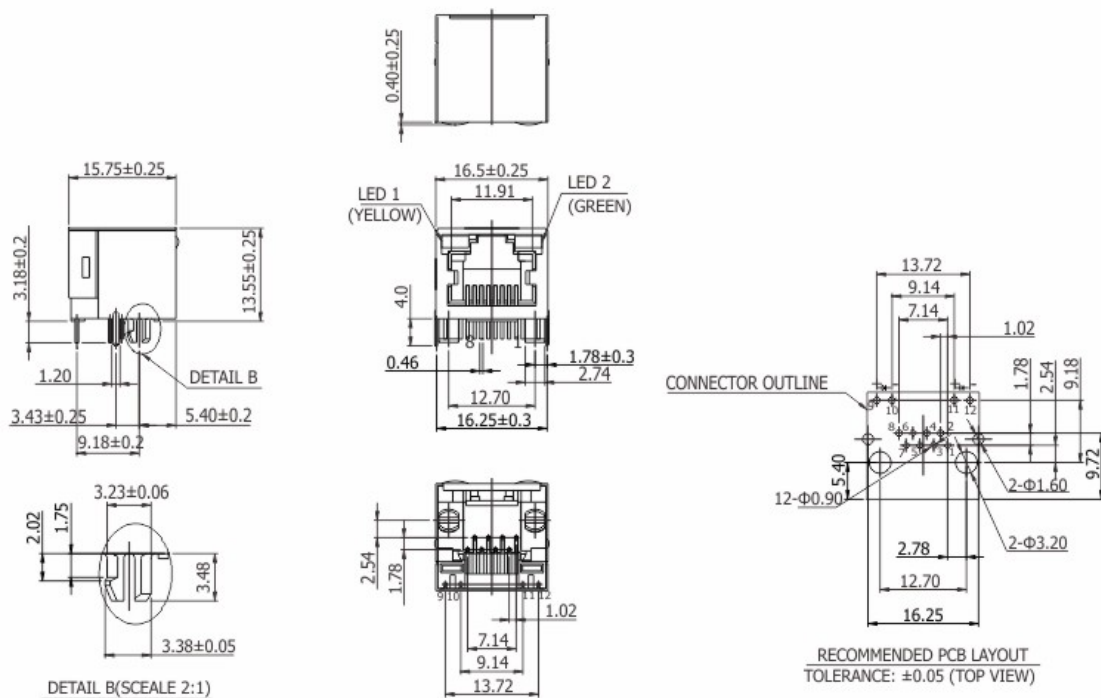
VOTAGE RATING: 150 VAC (R.M.S.) MAX

CURRENT RATING: 1.0 AMPERE MAX

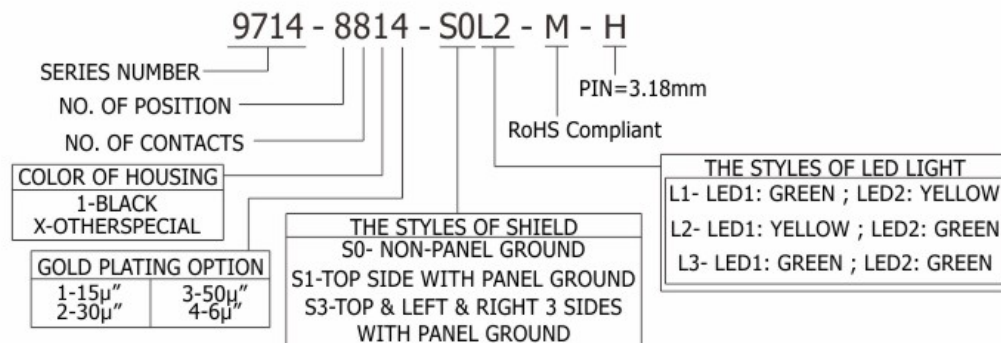
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

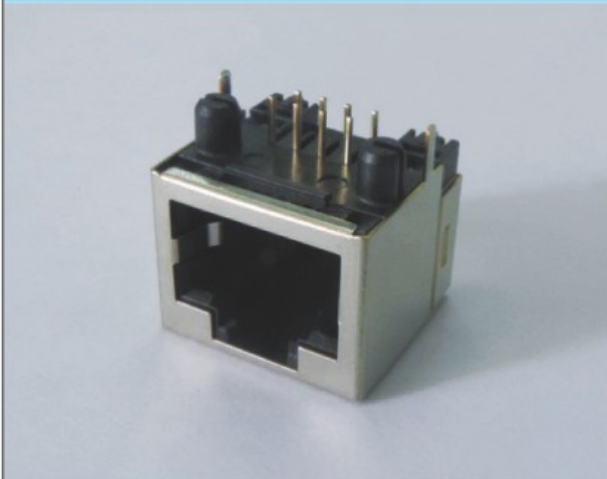
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

SHELL: 20μ" Min Nickel

3.ELECTRICAL

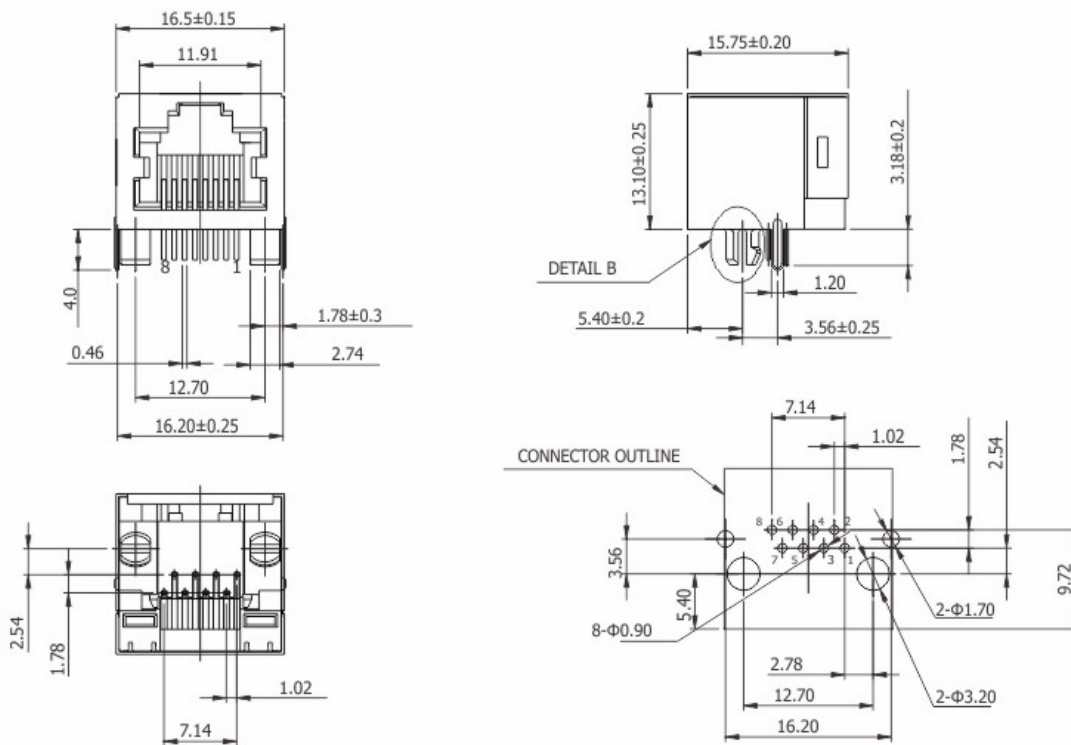
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

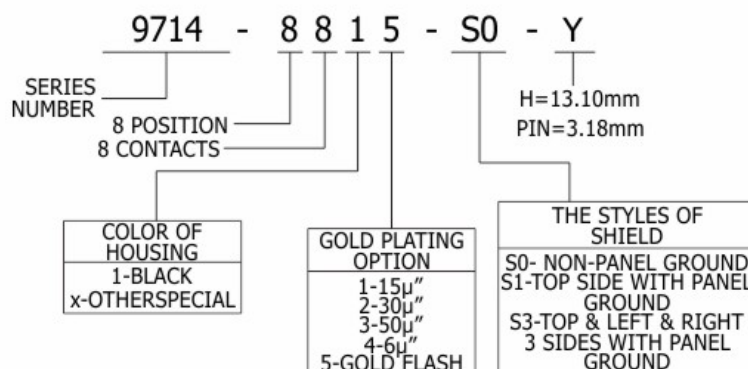
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING:

Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

SHELL: 20µ" Min Ni

3.ELECTRICAL

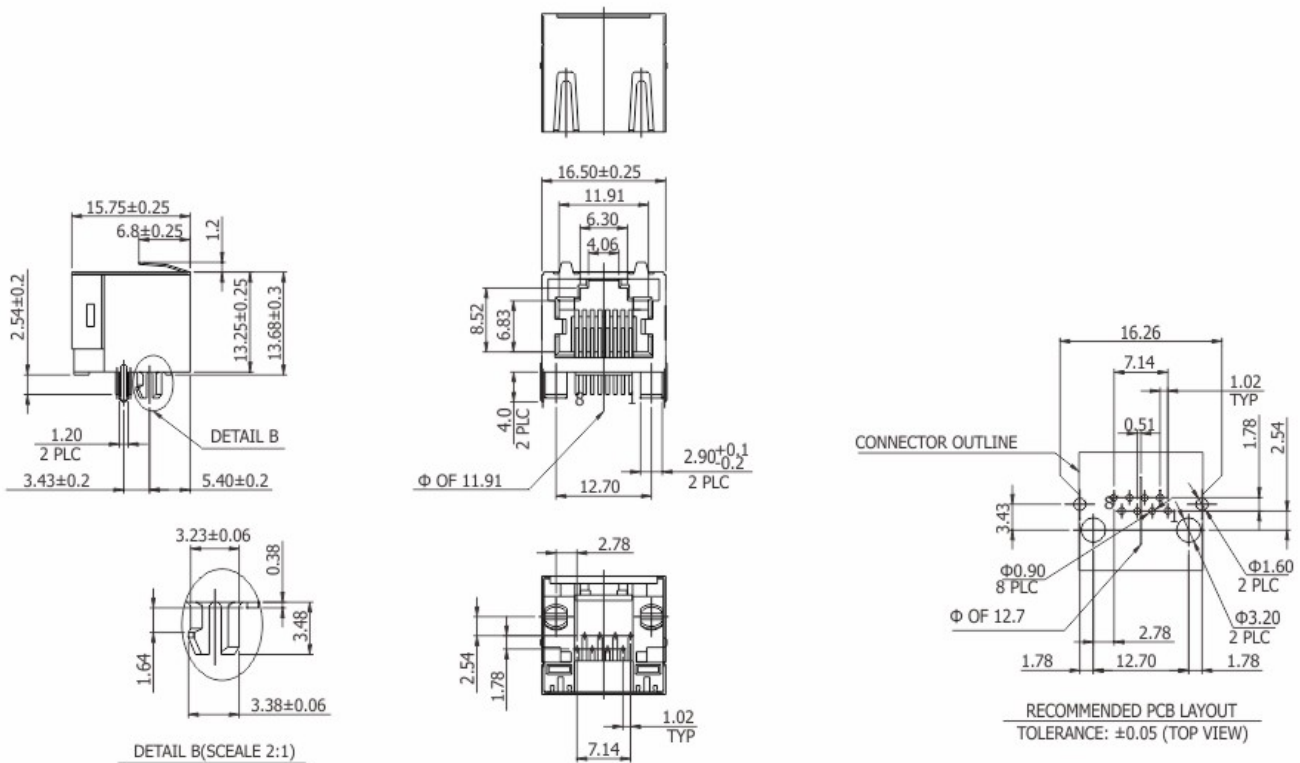
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

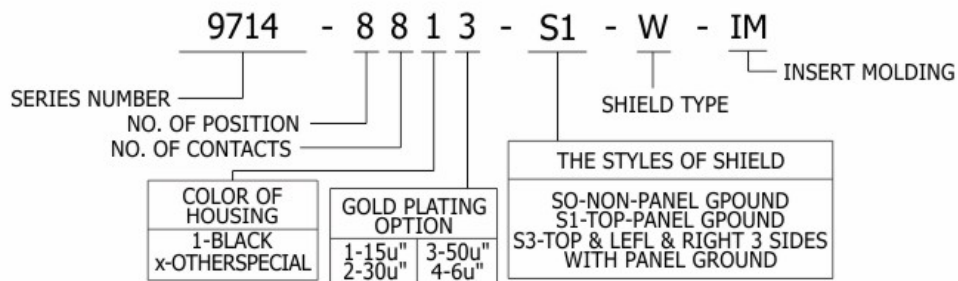
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

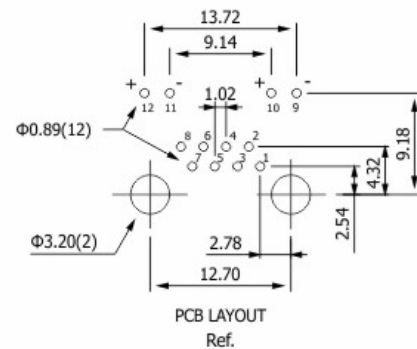
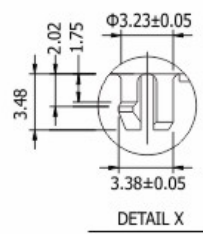
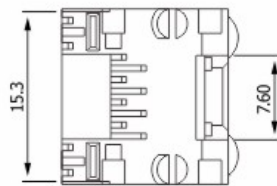
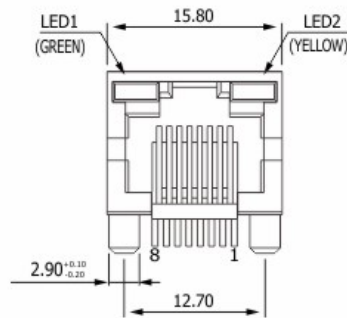
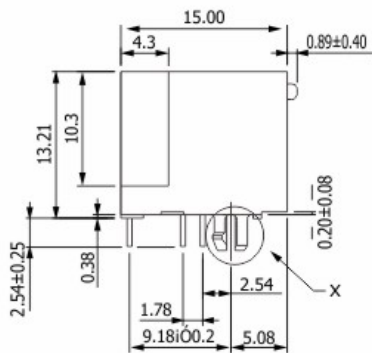
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
CONTACT: C5191-EH, T=0.35±0.02

2.PLATING:

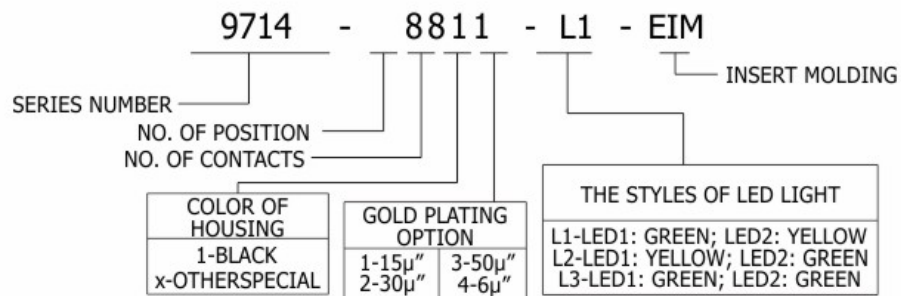
CONTACT: 30µ" Min Au over 50µ" Min Nickel

3.ELECTRICAL

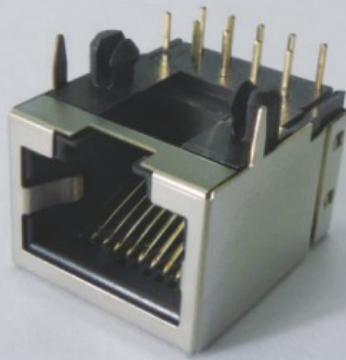
VOTAGE RATING: 150 VAC (R.M.S.)MAX
CURRENT RATING: 1.0 AMPERE MAX
INSULATION RESISTANCE: 500 MEGAOHMS MIN
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ48 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.20±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

SHELL: 20µ" Min Nickel

3.ELECTRICAL

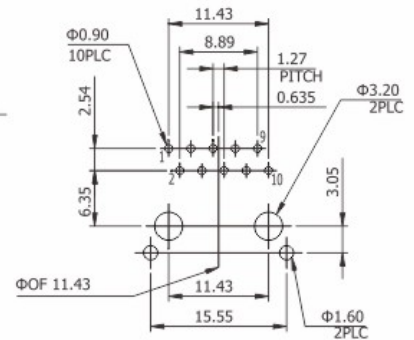
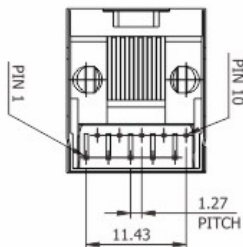
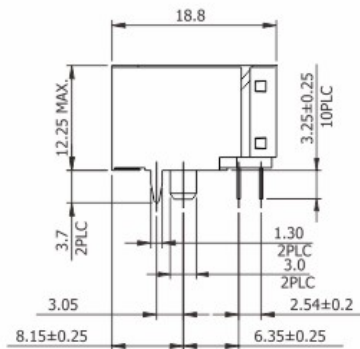
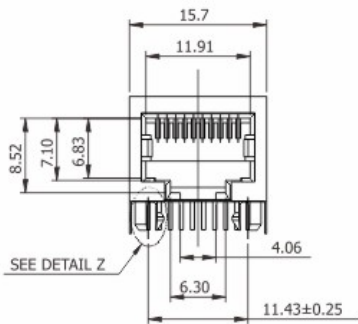
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

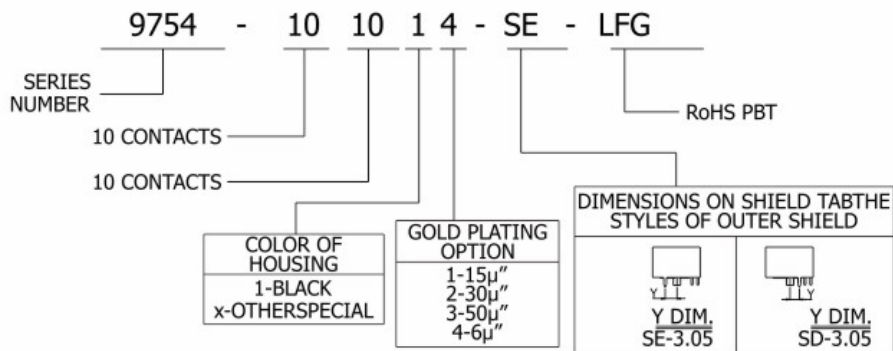
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



RECOMMENDED PCB LAYOUT
RECOMMENDED PCB THICKNESS: 1.6mm
TOLERANCE: ±0.05 (TOP VIEW)

Ordering Information



RJ45 1*2 PORTS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30u" Min Au over 50u" Min Nickel

SHELL: 20u" Min Ni

3.ELECTRICAL

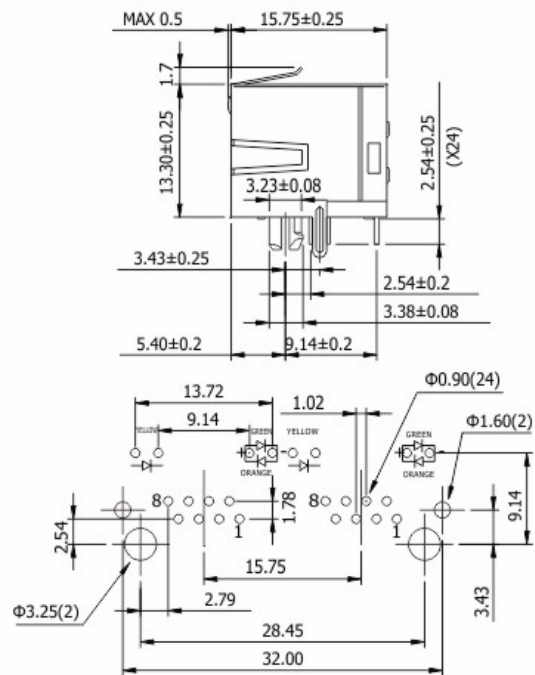
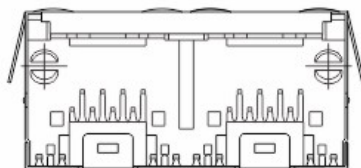
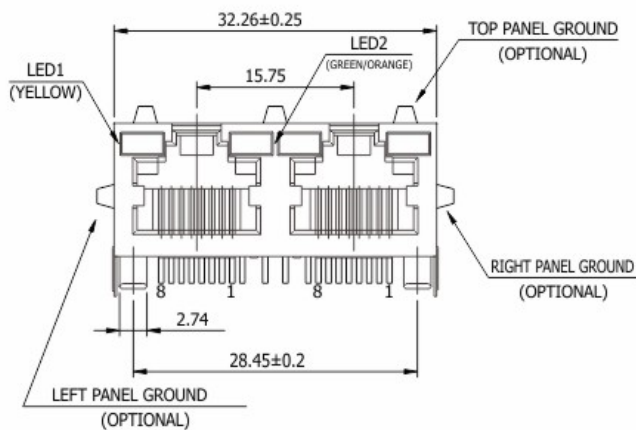
VOTAGE RATING: 150 VAC (R.M.S.) MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

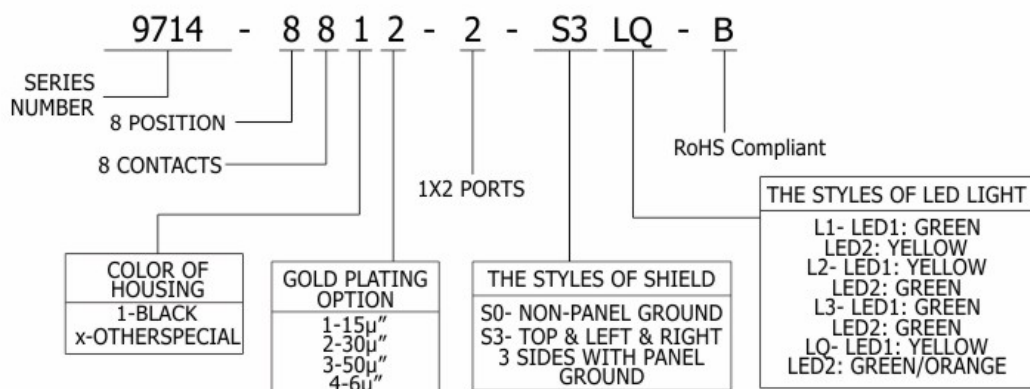
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C

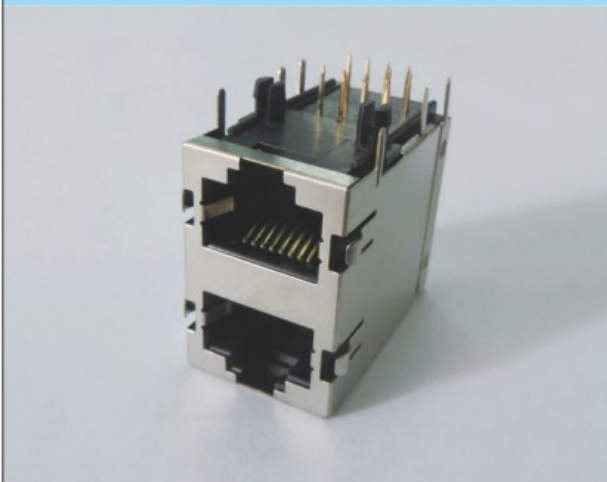


PCB LAYOUT (Ref.)

Ordering Information



RJ45 2*1 PORTS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

SHELL: 20μ" Min Nickel

3.ELECTRICAL

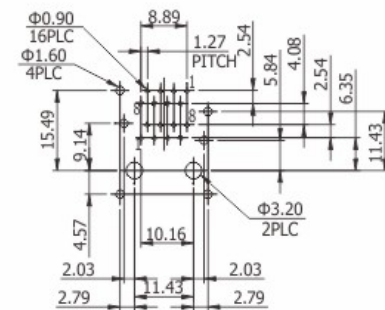
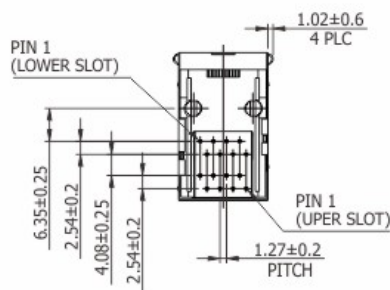
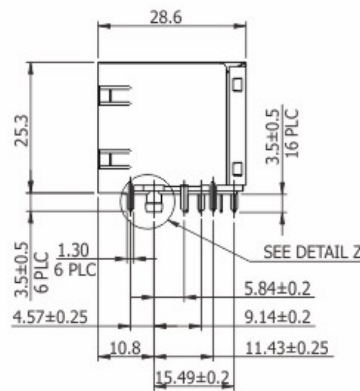
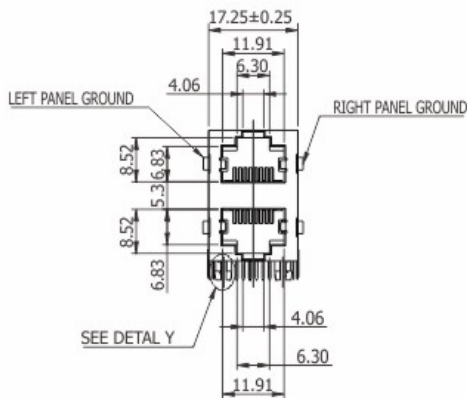
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

INSULATION RESISTANCE: 500 MEGAOHMS MIN

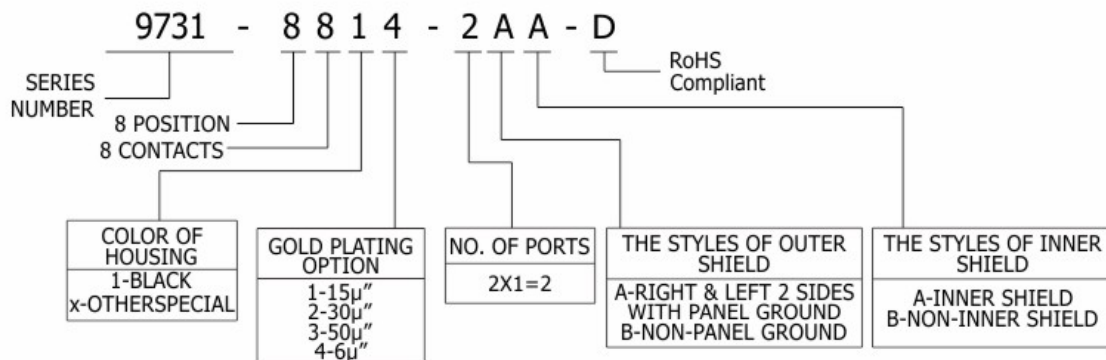
CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C

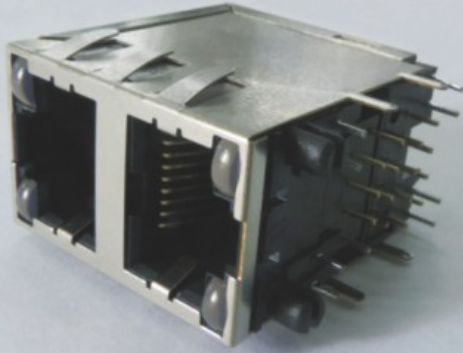


RECOMMENDED PCB LAYOUT
RECOMMENDED PCB THICKNESS: 1.6mm
TOLERANCE: ±0.05mm (TOP VIEW)

Ordering Information



RJ45 2*1 PORTS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
 CONTACT: C5191-EH, T=0.35±0.02
 SHELL: C2680, T=0.20±0.02

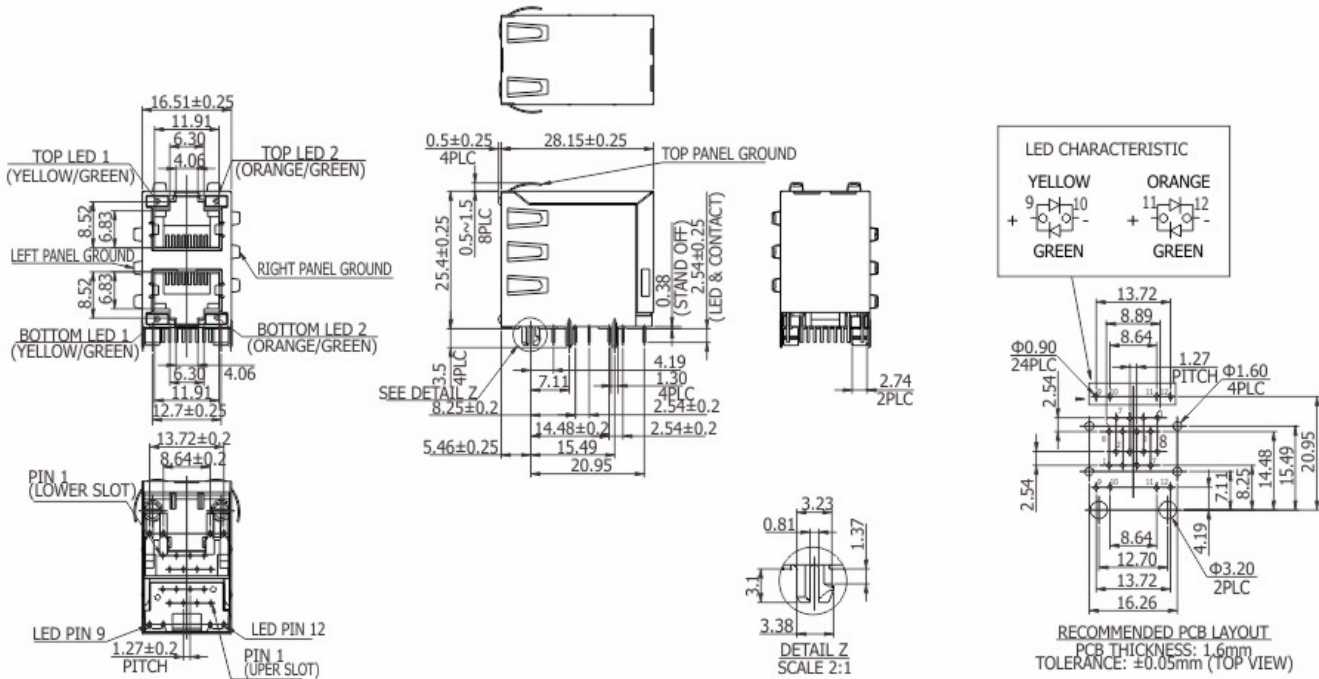
2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel
 SHELL: 20µ" Min Nickel

3.ELECTRICAL

VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS MIN
 CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM
 INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information

9766-8812-S3L76-DA

SERIES NUMBER
 NO. OF POSITIONS

NO. OF CONTACTS

COLOR OF HOUSING
 1= BLACK

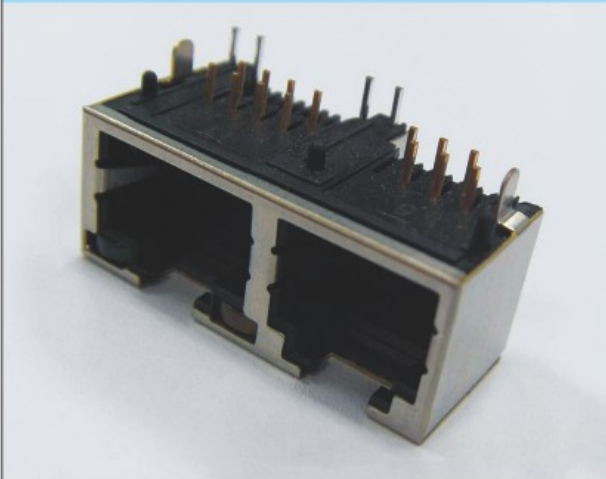
GOLD PLATING:
 1=15µ"
 2=30µ"
 3=50µ"
 4=6µ"

NONE LOGO, RoHS COMPLIANT

L76=LED1: YELLOW/GREEN
 LED2: ORANGE/GREEN

THE STYLE OF SHIELD
 S0=NON-PANEL GROUND
 S1=TOP SIDE WITH PANEL GROUND
 S3=TOP & LEFT & RIGHT 3 SIDES WITH PANEL GROUND

RJ45 & RJ11 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.45±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel

SHELL: 20μ" Min Nickel

3.ELECTRICAL

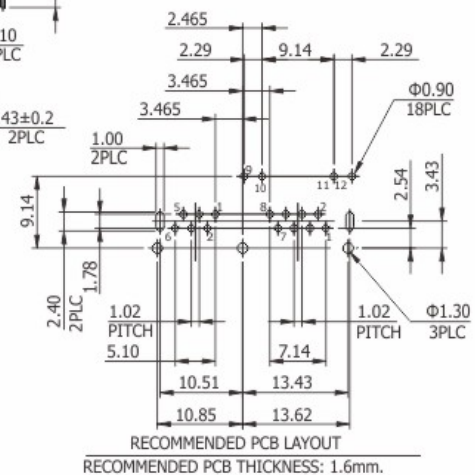
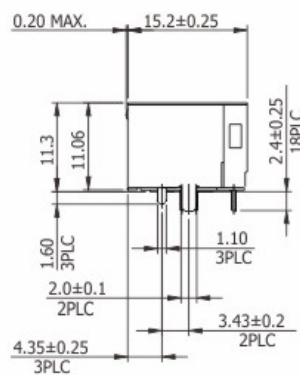
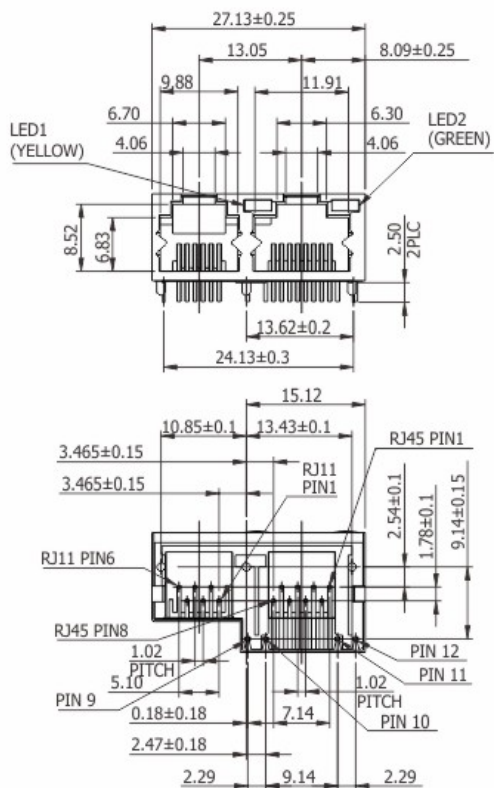
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

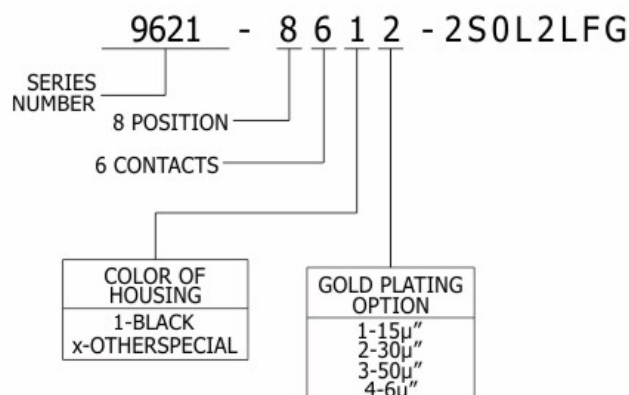
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

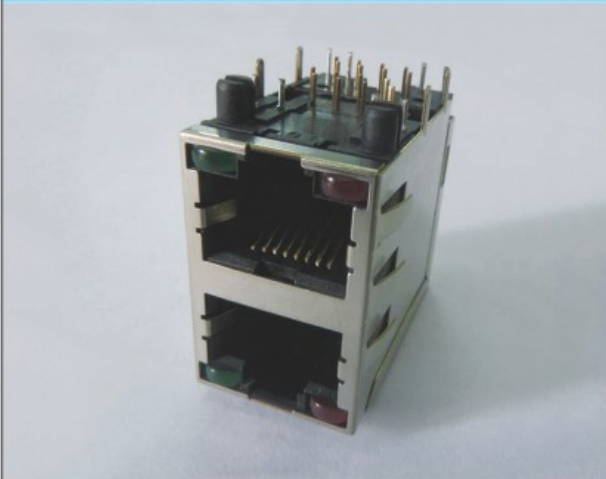
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 2*1 PORTS DIP TYPE



NOTE:

1.MATERIAL:

HOUSING:

Glass-Filled Thermoplastic high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.25±0.02

2.PLATING:

CONTACT: 30µ" Min Au over 50µ" Min Nickel

SHELL: 20µ" Min Nickel

3.ELECTRICAL

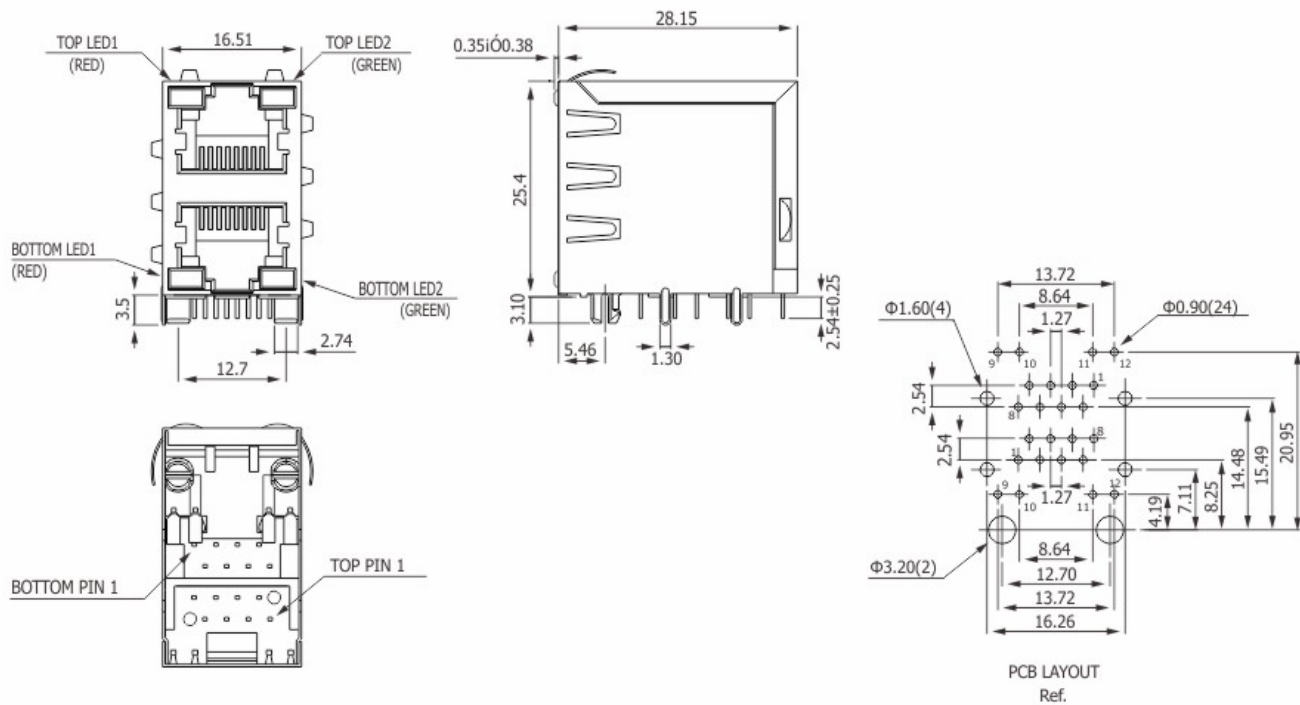
VOTAGE RATING: 150 VAC (R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

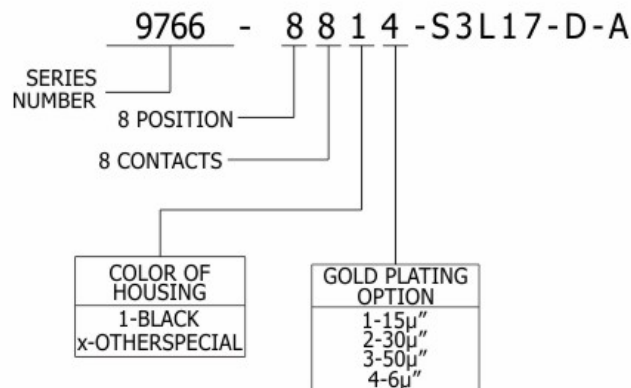
INSULATION RESISTANCE: 500 MEGAOHMS MIN

CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL

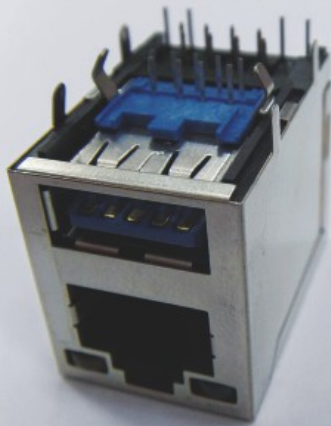
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 & USB 3.0 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic
high temperature, UL94V-0

CONTACT: C5191-EH, T=0.35±0.02

SHELL: C2680, T=0.2±0.02

PLATING:

CONTACT: 30μ" Min Au over 50μ" Min

Nickel

SHELL: 20μ" Min Nickel

2.USB:

HOUSING: Glass-Filled Thermoplastic
high temperature, UL94V-0

CONTACT: C2680, T=0.2±0.02

SHELL: C2680, T=0.3±0.02

PLATING:

CONTACT: 30μ" Min Au over 50μ" Min
Nickel

Solder AREA: 120μ" Min Tin over
50μ" Min Nickel

SHELL: 80μ" Min Nickel

3.ELECTRICAL

VOTAGE RATING: 150 VAC

(R.M.S.)MAX

CURRENT RATING: 1.0 AMPERE MAX

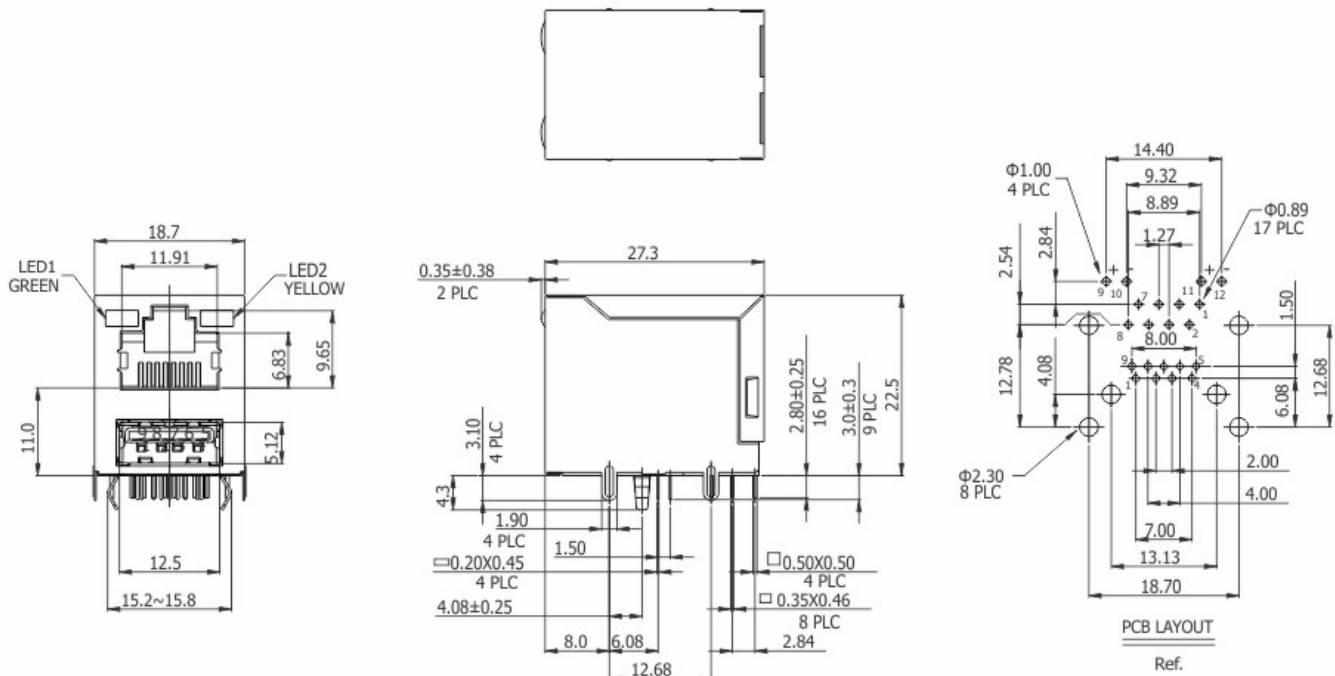
INSULATION RESISTANCE: 500

MEGAOHMS MIN

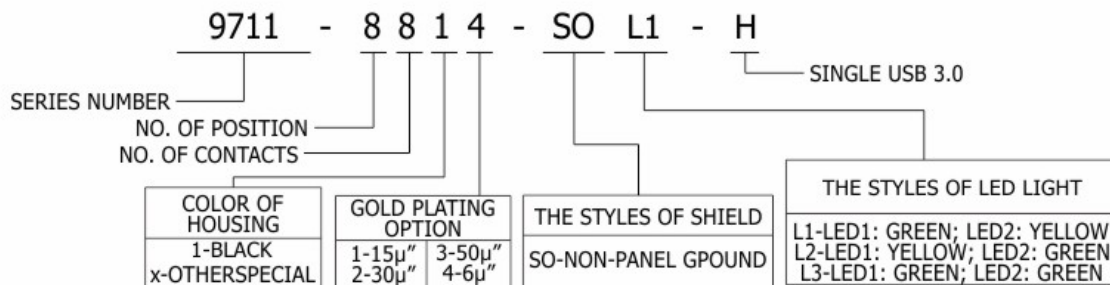
CONTACT RESISTANCE: 40

MILLIOHMS MAXIMUM INITIAL

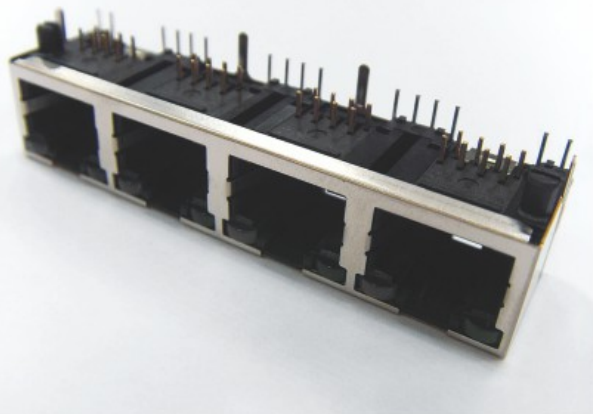
Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 1*4 PORTS DIP TYPE



NOTE:

1.MATERIAL:

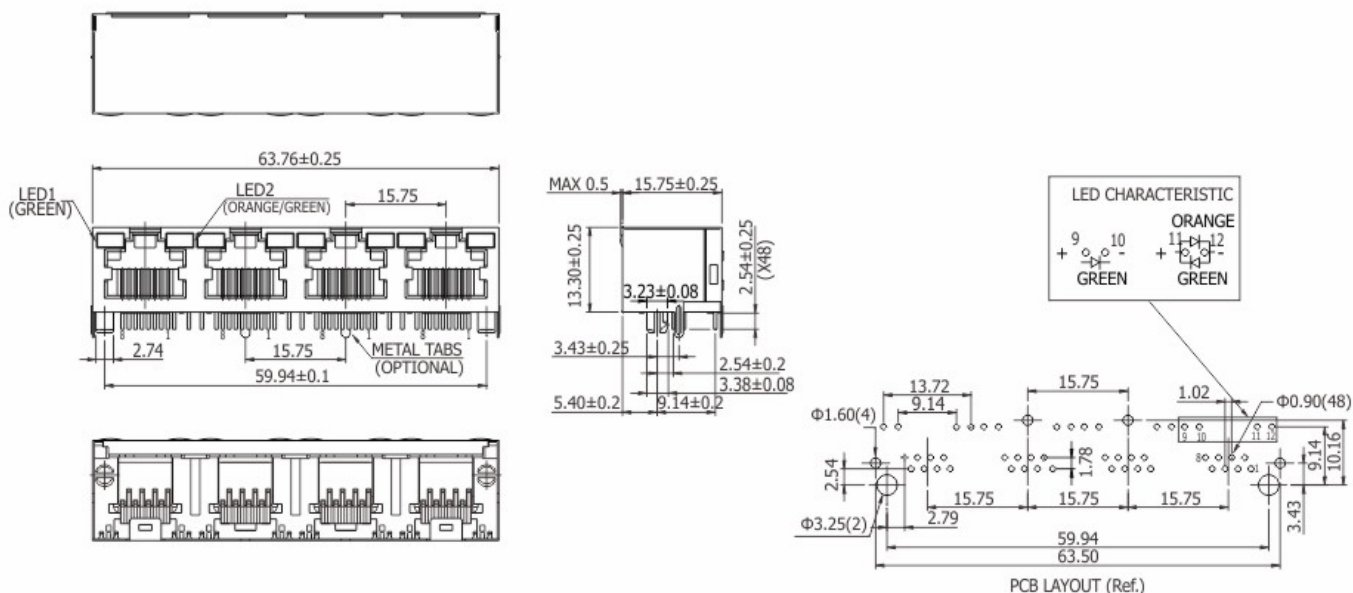
HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
 CONTACT: C5191-EH, T=0.35±0.02
 SHELL: C2680, T=0.25±0.02

2.PLATING:

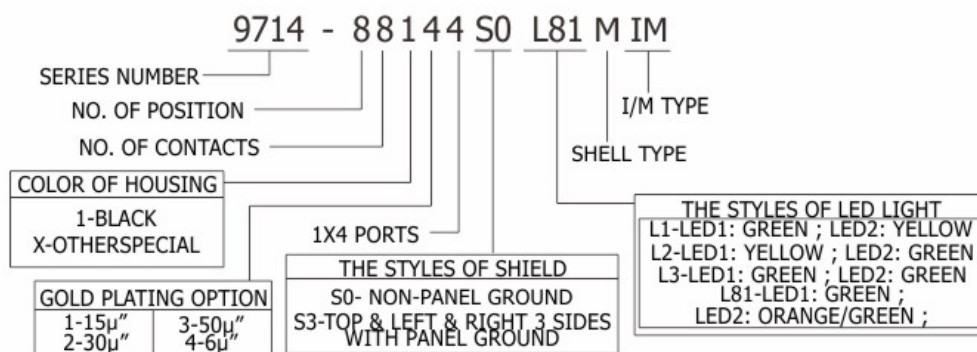
CONTACT: 30μ" Min Au over 50μ" Min Nickel
 SHELL: 20μ" Min Ni

3.ELECTRICAL

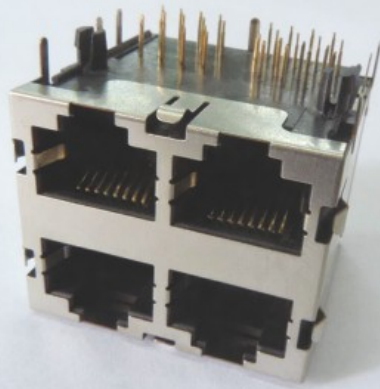
VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS MIN
 CONTACT RESISTANCE: 40 MILLIOHMS MAXIMUM INITIAL
 Storage Temperature: -20°C ~ +85°C



Ordering Information



RJ45 DIP TYPE



NOTE:

1.MATERIAL:

HOUSING: Glass-Filled Thermoplastic high temperature, UL94V-0
 CONTACT: C5191-EH, T=0.35±0.02
 SHELL: C2680, T=0.20±0.02

2.PLATING:

CONTACT: 30μ" Min Au over 50μ" Min Nickel
 SHELL: 20μ" Min Nickel

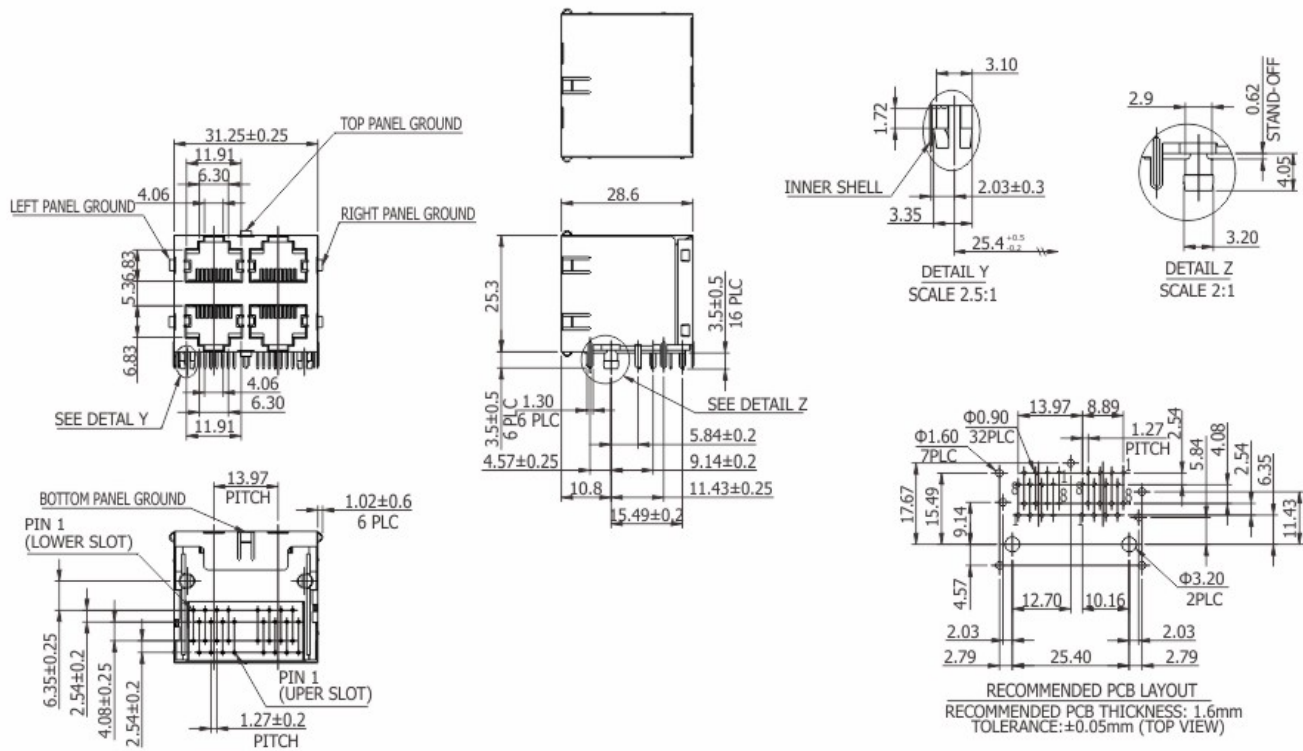
3.ELECTRICAL

VOTAGE RATING: 150 VAC (R.M.S.)MAX
 CURRENT RATING: 1.0 AMPERE MAX
 INSULATION RESISTANCE: 500 MEGAOHMS

MIN

CONTACT RESISTANCE: 40 MILLIOHMS
 MAXIMUM INITIAL

Storage Temperature: -20°C ~ +85°C



Ordering Information

